

AS3605

Multi-Standard Power Management Unit

1 General Description

The AS3605 is a highly-integrated CMOS power management device designed specifically for portable devices such as mobile phones, PDAs, CD players, digital cameras and other devices powered by 1-cell Li-Ion battery. It can be used for any mobile phone handset standards such as CDMA, WCDMA, GSM, GPRS, EDGE, UTMS and other Japanese or American standards.

The device incorporates low dropout regulators (LDOs), a DC/DC converter, a complete battery charger, and an audio power amplifier on one die.

The linear analog LDOs feature extremely high performance regarding:

- Noise typ 30µVRMs from 100Hz to 100kHz
- Line/Load Regulation < 1mV static, < 10mV transient
- Power Supply Rejection > 70dB @ 1kHz

The integrated Step Down DC/DC Converter does not require an external Schottky diode yet provides very high efficiency (up to 95%) throughout the whole operating range.

5 programmable current sources are included to control LED brightness.

A low-distortion audio power amplifier (1 Watt @ 8Ω) supports handsfree operation and HiFi ring-tones.

The device also features a battery charger including automatic trickle charging, and programmable constant voltage and current charging.

The AS3605 is controlled via a serial interface and integrates all necessary system specific functions such as Reset, Watchdog, and Power-On Detection.

Output voltages and start-up timings can be programmed via the internal OTP.

2 Key Features

- 8 Programmable High Performance LDOs
 - Four RF Low-Noise LDOs (1.8 to 3.35V, 150mA)
 - Two Analog Low-Noise LDOs (1.8 to 3.35V, 250mA)
 - One SIM Low-Power LDO (1.8 or 3.0V, 20mA)
 - One Low-Power LDO (2.5V, 10mA)
- Programmable High Efficiency DC/DC Converter
 - Step Down: 0.6 to 3.4V, up to 500mA with 2.2MHz
- Stereo Audio Power Amplifier
 - 0.5W @ 4Ω Stereo; 1W @ 8Ω Bridged
 - Digital Volume Control, 3dB Steps
 - Click- and Pop-Less Start-Up and Power-Down

- Battery Charger
 - Automatic Trickle Charging
 - Programmable Constant Current Charging
 - Programmable Constant Voltage Charging
 - Safety Functions (Low Battery Shutdown)
 - Over- and Under-Temperature Charge Disable
 - Operation without Battery
 - Can Regulate the Current Through the Battery or from the
 - Charger Input Overvoltage Protection (6V)
 - Shutdown even with Connected Charger
 - Charger Resume Operation
 - Charger Interrupts (Inserted, Removed, Overvoltage, Resume)
 - No-Battery Detection
- Momentary Power Loss Detection
 - Battery Supply Short-Interruption Detection (<200ms); (e.g., due to a dropped phone)
- Five Programmable Current Sources (3x40mA, 2x160mA)
 - 8-Bit (0.625 to 160mA)
 - Buzzer, Vibrator, LEDs
- Charge Pump (1:1 and 1:2 mode) 60mA @3.3V VBAT
- OTP programmable boot sequence
- Wide Battery Supply Range 3.0 to 5.5V
- Three Programmable General Purpose I/O Pins
- On-Chip Bandgap Tuning for High Accuracy (±1%)
- Integrated Programmable Watchdog (16 to 4080ms)
- Programmable Reset (0 to 70ms)
- Shutdown Current typ <10µA (2.5V Always On)
- Overcurrent and Thermal Protection
- 1.5 Watt Power Dissipation @T_A = 70°C

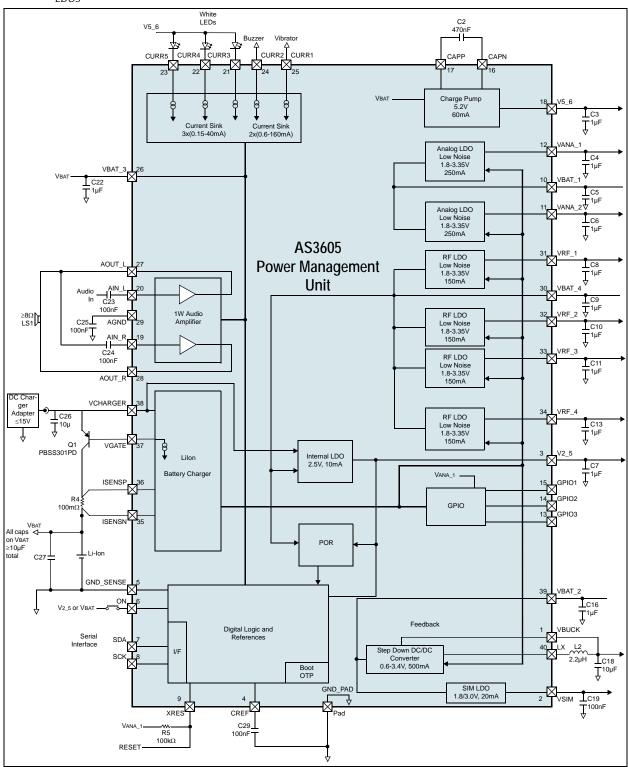
Packaging

QFN40 5x5mm, 0.4mm pitch

3 Application

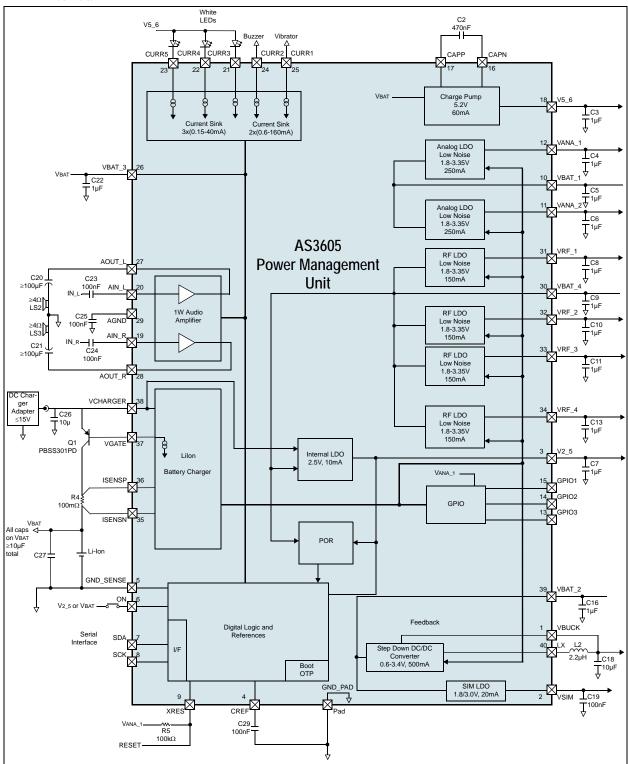
Multi-standard power management for mobile phones, PDAs, and any other 1-cell Li+ powered devices.

Figure 1. AS3605 Block Diagram. Option: Audio Amplifier In Differential Mode, Step Down DC/DC Converter as Pre-Regulator for Digital I DOs



Note: Refer to Table 33 for specifications of external components.

Figure 2. AS3605 Block Diagram. Option: Audio Amplifier in Stereo Single-Ended Mode, Digital LDOs Separated from Step Down DC/DC Converter



Note: Refer to Table 33 for specifications of external components.



Contents

1	General Description	. 1
2	Key Features	. 1
3	Application	. 1
4	Pin Assignments	. 6
	4.1 Pin Descriptions	7
5	Absolute Maximum Ratings	
	Electrical Characteristics	
7	Detailed Description	
	7.1 Battery Charge Controller	
	7.1.1 Charge Controller Operating Modes and Building Blocks	
	7.1.2 Charger Registers	
	7.2 Step Down DC/DC Converter	
	7.2.1 Low-Ripple, Low-Noise Operation	
	7.2.2 High-Efficiency Operation (Default Setting)	
	7.2.3 100% PMOS ON Mode for Low Dropout Regulation	19
	7.2.4 Low Power Mode	19
	7.2.5 Typical Performance Characteristics xxx	
	7.2.6 Step Down DC/DC Converter Registers	
	7.3 Low Dropout Regulators	
	7.3.1 RF and Analog Low Dropout Regulators	
	7.3.2 SIMCard Low Dropout Regulator	
	7.3.3 Low Power Low Dropout Regulator 7.3.4 Typical Performance Characteristics	
	7.3.5 LDO Registers	
	7.4 Charge Pump	
	7.4.1 Charge Pump Mode Switching	
	7.4.2 Charge Pump Registers	
	7.5 General Purpose Input/Output	
	7.5.1 GPIO Registers	
	7.5.2 Programmable Frequency Generator	
	7.5.3 Programmable Frequency Generator Registers	40
	7.5.4 Interrupt Function	
	7.5.5 Interrupt Registers	
	7.6 Current Sinks	
	7.6.1 Current Sink Registers	
	7.7 Audio Amplifier	
_	7.7.1 Audio Amplifier Registers	
8	System Supervisory Functions	51
	8.1 Reset	
	8.1.1 Reset Conditions	
	8.1.2 Reset Registers	
	8.1.3 Reset Cycle	
	8.1.4 res_con: Reset Control	
	8.2 Startup	
	8.2.1 Normal Startup	J ²

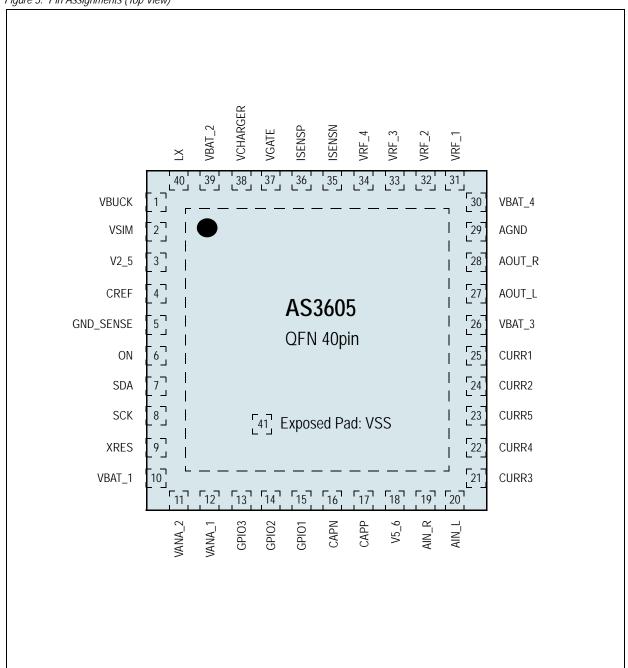


8.2.2 Programmable Startup Sequences	54
8.2.3 Startup from Battery Charger	
8.3 Protection Functions	54
8.3.1 TMP_SV: Temperature Supervision	54
8.3.2 Overtemperature Detection	55
8.3.3 Overtemperature Detection Register	55
8.4 Watchdog Block	56
8.4.1 Watchdog Registers	56
8.5 Internal Reference Circuits	58
8.5.1 Internal Reference Registers	58
8.6 Low Power Mode	59
8.7 Boot Sequence Detection	59
8.7.1 ON Detection Register	59
8.8 Serial Interface	60
8.8.1 Digital Input/Output DC/AC Characteristics	60
8.8.2 SPI Compatible Serial Interface	
8.8.3 I ² C Compatible Serial Interface	61
9 Register Map	65
10 External Parts List	68
11 Package Drawings and Markings	69
12 Ordering Information	72



4 Pin Assignments

Figure 3. Pin Assignments (Top View)





4.1 Pin Descriptions

Table 1. Pin Descriptions

Pin Name	Pin Number	Pin Type	Description
VBUCK	1	Analog Input	Sense input of the DC/DC converter.
VSIM	2	Analog Output	Output voltage of LDO VSIM; if used, connect a ceramic capacitor of 100nF (±20%).
V2_5	3	Analog Output	Output voltage of low power LDO V2_5; always connect a ceramic capacitor of $1\mu F$ ($\pm 20\%$) or $2.2\mu F$ ($\pm 100\%$ / $\pm 50\%$); do not load this pin during startup.
CREF	4	Analog Pin	Bypass capacitor for the internal voltage reference; always connect a capacitor of 100nF.
			Caution: Do not load this pin.
GND_SENSE	5	Analog Pin	Sensitive GND for Bandgap Voltage Reference.
ON	6	Digital Input	Input pin to startup the AS3605 (power on); internal pulldown; sense output in test mode.
SDA	7	Digital Input	SDA input/output in I ² C mode.
SCK	8	Digital Input	SCK input in I ² C mode.
XRES	9	Digital Input/Output / Open Drain (device can only pulldown this pin)	Bidirectional active low RESET pin; add an external pullup resistor.
VBAT_1	10	Supply Pin	Supply pin for Analog LDOs VANA_1 and VANA_2 as well as the charge pump; can be connected to VBAT or separate supply (3.0-5.5V).
VANA_2	11	Analog Output	Output voltage of one of Analog LDO VANA_2; if used as LDO, connect a ceramic capacitor of $1\mu F$ ($\pm 20\%$) or $2.2\mu F$ ($\pm 100\%$ / $\pm 50\%$).
VANA_1	12	Analog Pin	Output voltage of Analog LDO VANA_1; if used as LDO, connect a ceramic capacitor of $1\mu F$ ($\pm 20\%$) or $2.2\mu F$ ($+100\%$ / -50%).
GPIO3	13	Digital Input/Output	General purpose switchable 5V input/output.
GPIO2	14	Digital Input/Output	General purpose switchable 5V input/output.
GPIO1	15	Digital Input/Output	General purpose switchable 5V input/output.
CAPN	16	Analog Pin	Flying capacitor of the Charge Pump; if used connect a ceramic capacitor of 470nF (±20%) to this pin.
CAPP	17	Analog Pin	Flying capacitor of the Charge Pump; if used, connect a ceramic capacitor of 470nF (±20%) to this pin.
V5_6	18	Analog Pin	Output voltage of the Charge Pump; if used, connect a ceramic capacitor of $1\mu F$ ($\pm 20\%$) or $2.2\mu F$ ($\pm 100\%$ / -50%).
AIN_R	19	Analog Input	Audio Amplifier right-channel input.
AIN_L	20	Analog Input	Audio Amplifier left-channel input; sense output in test mode.
CURR3	21	Analog Input	Analog current sink input.
CURR4	22	Analog Input	Analog current sink input.
CURR5	23	Analog Input	Analog current sink input.
CURR2	24	Analog Input	Analog current sink input.
CURR1	25	Analog Input	Analog current sink input.
VBAT_3	26	Supply Pin	Supply pin for Current Sinks, and Audio Amplifier; always connect to VBAT.
AOUT_L	27	Analog Output	Audio Amplifier left-channel output.
AOUT_R	28	Analog Output	Audio Amplifier right-channel output.



8 - 73

Table 1. Pin Descriptions

Pin Name	Pin Number	Pin Type	Description
AGND	29	Analog Pin	Audio Amplifier reference GND; if the Audio Amplifier is used, connect a capacitor of 100nF (±10%) to this pin. Caution: Do not connect directly to VSS.
VBAT_4	30	Supply Pin	Supply pad for RF-LDOs VRF_1, VRF_2, VRF_3 and VRF_4; can be connected to VBAT or separate supply (3.0-5.5V).
VRF_1	31	Analog Output	Output voltage of RF LDO VRF_1; if used, connect a ceramic capacitor of 1 μ F (±20%) or 2.2 μ F (+100% / -50%).
VRF_2	32	Analog Output	Output voltage of RF LDO VRF_2; if used, connect a ceramic capacitor of 1 μ F (±20%) or 2.2 μ F (+100% / -50%).
VRF_3	33	Analog Output	Output voltage of RF LDO VRF_3; if used, connect a ceramic capacitor of 1 μ F (±20%) or 2.2 μ F (+100% / -50%).
VRF_4	34	Analog Output	Output voltage of RF LDO VRF_4; if used, connect a ceramic capacitor of 1 μ F (±20%) or 2.2 μ F (+100% / -50%).
ISENSN	35	Analog Input	Negative sensing input voltage for the external charging current shunt resistor.
ISENSP	36	Analog Input	Positive sensing input voltage for the external charging current shunt resistor.
VGATE	37	Analog Output	Control pin for the external battery charger MOSFET transistor.
VCHARGER	38	Analog Input	High voltage input coming from the Battery Charger; if the Battery Charger is used, connect a ceramic capacitor of $1\mu F$.
VBAT_2	39	Supply Pin	Supply pin for the Step Down DC/DC Converter and LDO VSIM; always connect to VBAT.
LX	40	Analog Output	Step Down DC/DC Converter switch output to coil
VSS	41	Vss	Ground pad (QFN40: exposed paddle).



5 Absolute Maximum Ratings

Stresses beyond those listed in Table 2 may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in Operating Conditions on page 10 is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 2. Absolute Maximum Ratings

Symbol	ymbol Parameter		Max	Unit	Comments
VIN_HV	High Voltage Pins	-0.3	18.0	V	Applicable for high voltage pins: VCHARGER, VGATE
VIN_MV	5V Pins	-0.3	7.0	V	Applicable for pins 5V pins: VBAT_1 - VBAT_4, V5_6, VBUCK, GPIO1 - GPIO3, CURR1 - CURR5, VANA_1, VANA_2, AIN_L, AIN_R, AOUT_L, AOUT_R, XRES, SCK, SDA, ON, and LX
VIN_LV	VIN_LV 3.3V Pins -0.3 5.		5.0	V	Applicable for 3.3V pins: VRF_1 - VRF_4, VSIM, CAPN, AGND, ISENSP, ISENSN, V2_5, CREF
lin	Input Pin Current	-25	+25	mA	At 25°C Norm: JEDEC JESD78C
	Humidity	5	85	%	Non-condensing
Continuous Po	ower Dissipation (T _A = +70°C)				
Рт	Continuous power dissipation		1.5	W	PT ¹ for QFN40 package
Electrostatic [Discharge				
VESD	Electrostatic Discharge HBM		±1.5	kV	Norm: JEDEC JESD22-A114F
Temperature F	Ranges and Storage Conditions				
Tj	Junction Temperature		+110	°C	
Tstrg	Storage Temperature Range	-55	+125	°C	
	Humidity non-condensing	5	85	%	
Temperature (soldering)				
	Package Body Temperature		260	°C	Norm IPC/JEDEC J-STD-020 ² , reflects moisture sensitivity level only
	Moisture Sensitive Level	;	3		Represents a maximum floor live time of 168h

^{1.} Depending on actual PCB layout and PCB used.

1.00

^{2.} The reflow peak soldering temperature (body temperature) is specified according IPC/JEDEC J-STD-020 "Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices.



6 Electrical Characteristics

Table 3. Operating Conditions

Symbol	Parameter	Min	Тур	Max	Unit	Notes
Тамв	AMB Ambient Temperature		25	85	°C	
VHV	High Voltage	0.0		15.0	V	Pins VCHARGER, VGATE
VBAT	VBAT Battery Voltage		3.6	5.5	V	For pins VBAT_1 - VBAT_4. During startup from external battery charger adapter, the battery voltage can be below 3.0V.
VANA_1	Periphery Supply Voltage for GPIO pins	1.8	OTP	3.35	V	Internally generated from VANA_1
Von	VON Activation voltage for ON pin		V2_5	VBAT	V	
V2_5	V2_5 Voltage on Pin V2_5		2.5	2.6	V	Internally generated
V5_6	Output Voltage of Charge Pump	4.9	5.2	5.6	V	2 x VBAT_1
lbat			195	260	μΑ	Normal operating current. With bit low_power_on = 0; only VANA_1 active, no additional external loads.
ILOWPOWER Low-Power Mode Current Consumption			110		μΑ	With bit low_power_on = 1; only VANA_1 active, no additional external loads.
lpoweroff	Power-Off Mode Current Consumption		10	20	μΑ	With bit power_off = 1; only V2_5 is active in power OFF mode. Not tested, guaranteed by design



7 Detailed Description

7.1 Battery Charge Controller

The AS3605 device serves as a standalone battery charge controller supporting rechargeable lithium ion (Li+) and) batteries. Requiring only a few external components, a full-featured battery charger with a high degree of flexibility can easily be realized. The main features of the controller

- Charge adapter detection
- Internal voltage regulator
- Low current (trickle) charging
- Constant current charging
- Constant voltage charging
- Overvoltage protection
- Battery presence indication
- Operation without battery

Figure 4. Charger Application Block Diagram

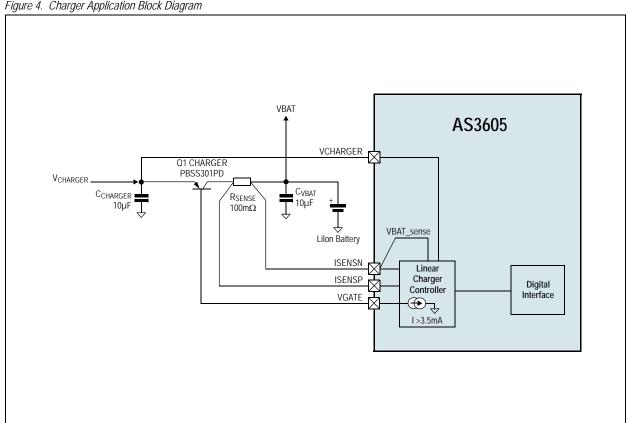


Table 4. Charger External Components

Symbol	Component	Value	Note
Q1	PNP power transistor	PBSS301PD or similar	hfe > 200 @ 0.8A
Rsense	Current sense resistor	$100 m\Omega$ ±1%, 125mW for ICHG < 1.5A	e.g. Vishay Dale WSL0805
Cchrg	Bypass capacitor on charger pin	10µF ±20%, X5R or X7R dielectric	
Сват	Minimum total capacitance parallel to battery	10µF, X5R or X7R dielectric	



7.1.1 Charge Controller Operating Modes and Building Blocks

Charge Adapter Detection. The charge controller uses an integrated detection circuit to determine if an external charge adapter has been applied to the VCHARGER pin. If the adapter voltage exceeds the battery voltage at pin VBAT by VCHDET the ChDet bit in the ChargerStatus register will be set. The detection circuit will reset the charge controller (bit ChDet is cleared) as soon as the voltage at the VCHARGER pin drops to only VCHMIN above the battery voltage. In case the AS3605 device is reset the charge controller will also be reset, even if a charge adapter is applied to the VCHARGER pin.

Low Current (trickle) Charging. Trickle charge mode is started when an external charge adapter has been detected and the battery voltage at pin VBAT is below the VuvLo threshold; bits ChAct and Trickle will be set in the ChargerStatus register. In this mode the charge current will be limited to TrickleCurrent[1:0] (set in the ChargerControl1 register) to prevent undue stress on either the battery or any of the charger components in case of deeply discharged batteries. Once VUVLO has been exceeded, the charger will change over to constant current charging (Trickle is cleared) and switch on the device.

Constant Current Charging. Constant current charging is initiated by setting ChEn in the ChargerControl1 register. Note that ChEn is set by default to enable operation of the device without a battery connected to the system. The ChAct bit is set when the charger has started, and the charge current will be limited to ConstantCurrent[3:0] (set in the ChargerControl1 register) by the battery charge controller. When the battery approaches full charge, its voltage will exceed the charge termination threshold VCHOFF. VCHOFF depends on the Li4v2 bit in the ChargerControl2 register. The charging action will either be terminated (EOC bit will be set) or a top-off charge will be started (CVM will be set).

Constant Voltage Charging. Constant voltage charge mode is initiated and the CVM bit will be set when the VCHOFF threshold has been reached.

The charge current is monitored during constant voltage charging. It will be decreasing from its initial value during constant current charging and eventually drop below the value set by **TrickleCurrent[1:0]** in the **ChargerControl1** register. If the measured charge current is less than or equal to **TrickleCurrent[1:0]**, the charging cycle is terminated and **EOC** is set.

Battery Presence Indication and Operation Without Battery. After EOC state is reached a timer for NOBAT detection is started. If there is no battery present, the voltage will drop to V_{NOBAT_REG}. Depending on the load on VBAT and the capacitor on VBAT this might take some mseconds to 1 second. If the RESUME mode is enabled (Bit **resume_disable=**0), the charger will restart charging (ConstantCurrent charging) after 100msec.

The 100msec dead time is necessary to get a battery oscillation frequency of below 10Hz, if there is no battery present.

If the NOBAT detection timer is below 2 seconds after reaching EOC state, and this happens 2 times in serial, the NOBAT bit in **ChargerStatus** register is set. If a battery is inserted, then the bit will be reset after the timer exceeds the 2 seconds.

Charger Overvoltage Protection. This blocks checks if the charger voltage is above 6.05V or 6.45V if **ChOvH** is 1. If the status bit **ChOv** is 1 when **ChOvEn** is 1, the charger will shut down by clearing the **ChEn** bit and an interrupt will be generated.

Table 5. Charger Parameters

Symbol	Parameter	Min	Тур	Max	Unit	Notes
VCHDET	Charger detection threshold		75	105	mV	Hysteresis is > 40mV
VCHMIN	Charger detection threshold	0	20	35	IIIV	Trysteresis is > 40111V
Vсноvн	VCHARGER overvoltage detection	6.2	6.45	6.71	V	ChOvH = 1
VCHOVH	VCHAROLK OVERVOITAGE DETECTION	5.81	6.05	6.29	V	ChOvH = 0
Vuvlo	Undervoltage lockout threshold		3.1		V	VBAT rising
VUVLO	Undervoltage lockout threshold		2.8		V	VBAT falling
VCHOFF	Charge termination threshold	4.158	4.20	4.242	V	Li+ Battery: Li4v2 = 1
VCHOFF	Charge termination threshold		4.10		V	Li+ Battery: Li4v2 = 0
VNOBATREG	"No battery" regulation voltage		3.85		V	Li+ Battery: Li4v2 = 1
VINORALKEG	ivo battery regulation voltage		3.75		٧	Li+ Battery: Li4v2 = 0
VDECUME ON	Character and the sale and		3.85		V	Li4v2 = 1
VRESUME_ON	Charger resume on threshold		3.75		V	Li4v2 = 0



Table 5. Charger Parameters

Symbol	Parameter	Min	Тур	Max	Unit	Notes
VRESUME OFF	Charger resume off threshold		4.02		V	Li4v2 = 1
V KESUWE_OFF	Charger resume on threshold		3.92		V	Li4v2 = 0
IGATE_OFF	Current into pin GATE, if charger disabled	0		0.4	μΑ	VCHARGER=5V
IGATE_ON	Current into pin GATE, if charger enabled and operation in low dropout mode (low VcE)	3.5	5		mA	VCHARGER=5V

7.1.2 Charger Registers

Table 6. Charger Register Summary

Name	Addr.	b7	b6	b5	b4	b3	b2	b1	b0	Page
LDO_CHG	10h					EOCCui	rrent[1:0]			14
ChargerControl1	14h	ChOvEn	TrickleCu	ırrent[1:0]		ConstantCurrent[3:0]			ChEn	13
ChargerControl2	16h	ChOv	ChOvH	NA	Li4v2	resume_d isable				14
ChargerStatus	35h	NA	NoBat	EOC	CVM	Trickle	NA	ChAct	ChDet	15

ChargerControl1 Register (Address 14h).

Addr: 14	h	ChargerControl1						
Bit Bit Name		Default	Access	Bit Desc	ription			
_	21.5			0	Disable charging			
0	ChEn	1b	R/W	1	Enable charging			
				0	0mA + Trickle_current			
				1	50mA + Trickle_current			
				2	100mA + Trickle_current			
			3 150mA + Trickle_current 4 200mA + Trickle_current	3	150mA + Trickle_current			
				200mA + Trickle_current				
				5	250mA + Trickle_current			
				6	300mA + Trickle_current			
4.1	Constant Current[2,0]	OTP	DAM	7	350mA + Trickle_current			
4:1	ConstantCurrent[3:0]	UIP	R/W	8	400mA + Trickle_current			
				9	450mA + Trickle_current			
				А	500mA + Trickle_current			
				В	550mA + Trickle_current			
				С	600mA + Trickle_current			
				D	650mA + Trickle_current			
				Е	700mA + Trickle_current			
				F	750mA + Trickle_current			



Addr: 14	h	ChargerControl1					
Addi. 14	Auui. 1411						
Bit Bit Name		Default	Access	Bit Description			
		OPT		0	50mA		
/	TrickleCurrent[1:0]		R/W	1	100mA		
6:5				2	150mA		
				3	200 mA		
7	ChOvEn	1	R/W	0	Disable the Charger Overvoltage protection		
/				1	Enable the Charger Overvoltage protection		

LDO_CHG Register (Address 10h).

Addr: 10h		LDO_CHG						
		Adjusts EOC curre	Adjusts EOC current of Charger.					
Bit Bit Name		Default	Access	Bit Descrip	tion			
		00	R/W	00	EOC Current = Trickle Current			
3:2	F0.00			01	EOC Current = Trickle Current + 18mA			
3:2	EOCCurrent[1:0]			10	do not use			
				11	EOC Current = Trickle Current + 33mA			

ChargerControl2 Register (Address 16h).

Addr: 16h		ChargerContro	12				
Addi. 1011							
Bit	Bit Name	Default	Access	Bit Desc	cription		
2:0	-	NA	NA				
3	resume_disable	0	R/W	0	Enable Resume in EOC state		
3	resume_uisable	U	FX/VV	1	Disable Resume in EOC state		
4	Li4v2	1	1 500		VCHOFF = 4.1V for Li+ battery cells with coke anode		
4	L14VZ		R/W	1	VCHOFF = 4.2V for Li+ battery cells with graphite anode		
5	-	NA	NA				
,	ChOull	1	DAM	0	Sets low threshold for Over voltage protection (typ. 6.05V)		
6	ChOvH	1	R/W	1	Sets high threshold for Over voltage protection (typ. 6.45V)		
7	ChOv	NA	R	Indicates Charger overvoltage condition			



ChargerStatus Register (Address 35h).

۸ ماماس ۲۲	'L	ChargerStatus						
Addr: 35	on	Read only						
Bit	Bit Name	Default	Default Access Bit Description					
0	ChDet	NA	R	Bit is set when external charge adapter has been detected				
1	ChAct	NA	R	Bit is set when charger is operating				
2	-	NA						
3	Trickle	NA	R	Bit is set when charger is in trickle charge mode				
4	CVM	NA	R	Bit is set when charger is in top-off charge mode				
5	EOC	NA	R	Bit is set when charging has been terminated. Bit is cleared automatically when ChEn is cleared.				
6	NoBat	NA	R	Bit is set when battery detection circuit indicates that no battery is connected to the system. Bit is cleared automatically when a battery is connected or when ChEn is cleared.				
7	-	NA	NA					



7.2 Step Down DC/DC Converter

The step-down converter is a high-efficiency fixed frequency current mode regulator. By using low resistance internal PMOS and NMOS switches, efficiency up to 95% can be achieved. The fast switching frequency allows using small inductors, without increasing the current ripple. The unique feedback and regulation circuit guarantees optimum load and line regulation over the whole output voltage range, up to an output current of 500mA, with an output capacitor of only $10\mu F$. The implemented current limitation protects the DC/DC Converter and the coil during overload condition.

Figure 5. Step Down DC/DC Converter Block Diagram

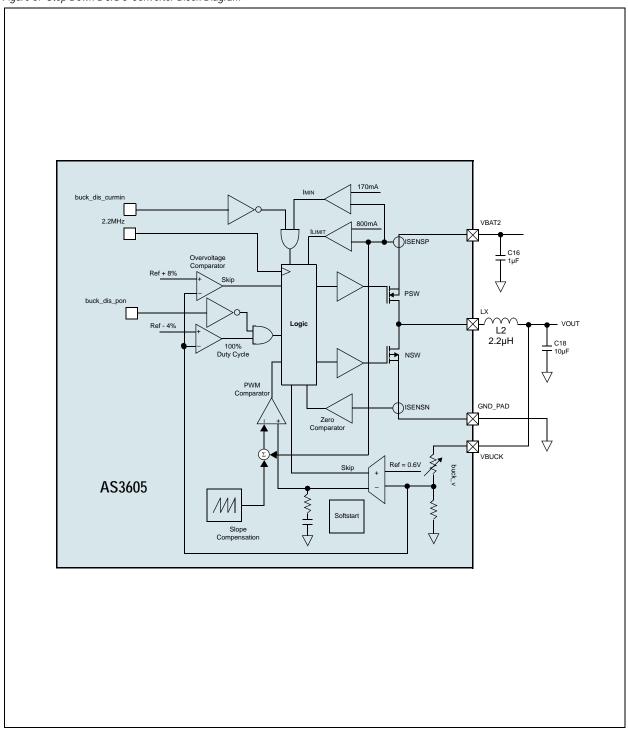




Table 7. Step Down DC/DC Converter Parameters

Symbol	Parameter	Min	Тур	Max	Unit	Notes
VIN	Input Voltage	3.0		5.5	V	Pin VBAT_2
Vout	Regulated Output Voltage	0.6		3.4	V	Sense pin VBUCK
VOUT TO	Output Voltage Tolerance	-50		50	mV	Sense pin VBUCK; Output Voltage < 1.6V
VOUT_TOL	Output voltage Tolerance	-3%		3%		Sense pin VBUCK; Output Voltage > 1.6V
ILIMIT	Current Limit		900		mA	Supply current into PMOS transistor
Rpsw	PSW On-Resistance			0.5	Ω	
Rnsw	NSW On-Resistance			0.5	Ω	
ILOAD	Load Current	0		500	mA	
fsw	Switching Frequency		2.2		MHz	
Соит	Output Capacitor		10		μF	Ceramic
Lx	Inductor		2.2		μΗ	
h	Efficiency		90		%	ILOAD = 100mA, VOUT = 2.3V, VBAT = 3V
			250			Operating Current; No Load
IVDD_DCDC	Current Consumption		100		μΑ	Quiescent Current; Low-Power Mode
			0.1			Shutdown Current
tmin_on	Minimum ON Time		80		ns	
tmin_off	Minimum OFF Time		40		ns	

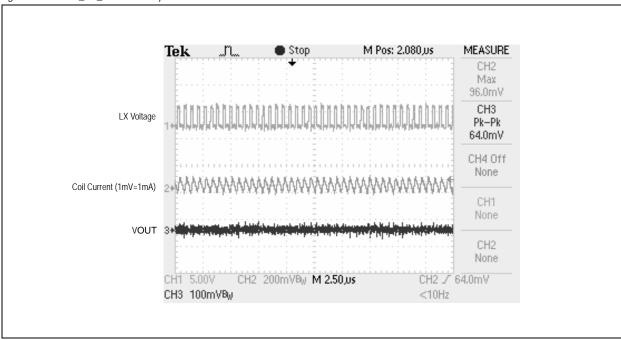
To allow optimized performance in different applications, there are bit settings possible, to get the best compromise between high efficiency and low input/output ripple.

7.2.1 Low-Ripple, Low-Noise Operation

Low-ripple, low-noise operation can be enabled by setting bit **buck_dis_curmin** = 1. In this mode there is no minimum coil current necessary before switching OFF the PMOS. As result, the ON time of the PMOS will be reduced down to tMIN_ON at no or light load conditions, even if the coil current is very small or the coil current is inverted. This results in a very low ripple and noise (but decreased efficiency) at light loads, especially at low input-to-output voltage differences.

Note: Because of the inverted coil current in that case the regulator will not operate in pulse skip mode.

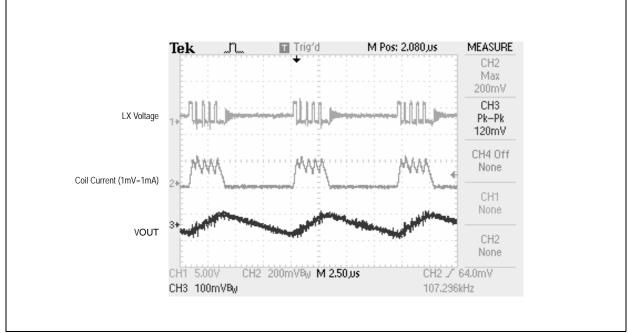
Figure 6. Bit buck_dis_curmin = 1 Operation



7.2.2 High-Efficiency Operation (Default Setting)

High-efficiency operation is enabled by setting bit buck_dis_curmin = 0. In this mode there is a minimum coil current necessary before switching OFF the PMOS. As result there are less pulses at low output load necessary, and therefore the efficiency at low output load is increased. This results in higher ripple, and noisy pulse skip operation up to a higher output current.

Figure 7. Bit buck_dis_curmin = 0 Operation



Note: It is possible to switch between these two modes during operation, i.e.:

Bit buck_dis_curmin = 0: System is in idle state. No audio or RF signal. Decreased supply current preferred. Increase ripple doesn't effect system performance.



Bit **buck_dis_curmin** = 1: System is operating. Audio signal on and/or RF signal used. Decreased ripple and noise preferred. Increased power supply current can be tolerated.

7.2.3 100% PMOS ON Mode for Low Dropout Regulation

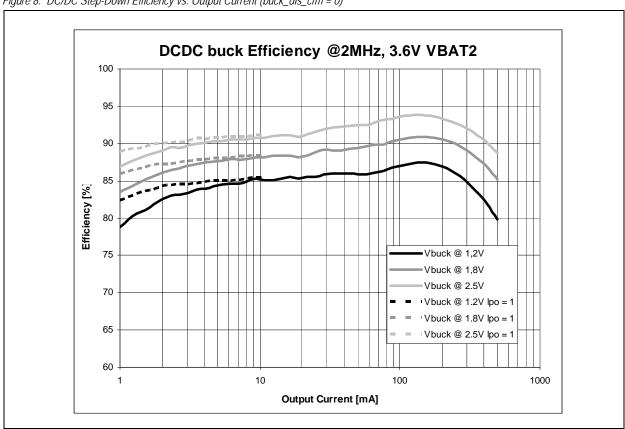
For low input-to-output voltage difference bit **buck_dis_pon** can be set to allow 100% duty cycle of the PMOS transistor, if the output voltage drops by more than 4% below regulation.

7.2.4 Low Power Mode

Bit **buck_Ipo** can be set all the time. This mode allows internal power down, of not used blocks during pulseskip mode, which results in a better efficiency at light output loads.

7.2.5 Typical Performance Characteristics

Figure 8. DC/DC Step-Down Efficiency vs. Output Current (buck_dis_cfm = 0)



7.2.6 Step Down DC/DC Converter Registers

The Step Down DC/DC Converter is controlled by the registers listed in Table 8.

Table 8. Step Down DC/DC Converter Register Summary

Name	Addr.	b7	b6	b5	b4	b3	b2	b1	b0	Page
Step Down Voltage/Test Modes	01h		-			bu	ck_v			20
Reg Power	09h		-	buck_on	ldo_sim_ on			ldo_ana2_ on	ldo_ana1 _on	20
Step Down Configuration	17h	buck_dis_ curmin	buck_ dis_pon	buck_lpo	-	-	buck_ dis_n	buck_ nsw_on	buck_ psw_on	20



Step Down Voltage Register (Address 01h).

Addr: 01h		Step Down Volt	Step Down Voltage/Test Modes						
Addi. Uili	Sets the output voltage of the Step Down DC/DC Converter.				/DC Converter.				
Bit	Bit Name	Default	Access	Bit Description					
			Controls the voltage selection for the Step Down DC/DC Converter.						
			ļ	000000	0.6V				
5:0	buck_v	Boot ROM	R/W		(LSB = 50mV)				
			111000- 111111	3.4V					
7:6	-	NA	NA						

Reg Power Register (Address 09h).

Addr: 09h		Reg Power						
Auui. 0911		Enables/disables voltage regulators.						
Bit	Bit Name	Default	Access	Bit Descrip	tion			
0	ldo_ana1_on	Boot ROM	RW	Refer to pag	ge 28			
1	ldo_ana2_on	Boot ROM	RW	Refer to page 28				
3:2	-	NA	NA					
4	ldo_sim_on	Boot ROM	RW	Refer to pag	ge 28			
				Enables the	Step Down DC/DC Converter.			
5	buck_on	Boot ROM	R/W	0	Step Down DC/DC Converter is OFF.			
				1	Step Down DC/DC Converter is ON.			
7:6	-	NA	NA					

Step Down Configuration Register (Address 17h).

Addr: 17h		Step Down Co	onfiguration						
Auui. 171	'	Configures the	operation mod	e of the Step Down DC/DC Converter.					
Bit	Bit Name	Default	Access	Bit Description					
				Activate PS	W (0.5 Ω PMOS) only if buck_on and buck_nsw_on = 0.				
0	buck_psw_on	0	0 R/W		Default setting. P-Channel switching transistor is controlled by the DC/DC Converter.				
			1	Turns on P-Channel switching transistor. Bits buck_on and buck_nsw_on must both = 0.					
				Activates NSW (0.5 Ω NMOS) only if buck_on = 0 and buck_psw_on = 0.					
1	buck_nsw_on	0	R/W	0	Default setting. N-Channel switching transistor is controlled by the DC/DC Converter.				
				1	Turns on N-Channel switching transistor. Bits buck_on and buck_psw_on must both = 0.				
0	level eller	0	DAM	0	Default setting. Normal operation of The synchronous rectifier.				
2	buck_dis_n	0	R/W	1	The synchronous rectifier is disabled (NSW is always OFF).				
	3 - 0 RW		0						
3			1						



21 - 73

Addr: 17l	<u> </u>	Step Down Co	onfiguration				
Auui. 171	1	Configures the	operation mod	e of the Step	Down DC/DC Converter.		
Bit	Bit Name	Default	Access	Bit Description			
4	-	0	R/W	0			
				1			
_	book less		D/11	0	Low-power mode disabled.		
5	buck_lpo	0	R/W	1	Low-power mode enabled.		
			Step down PON feature control.				
6	buck_dis_pon	0	R/W	0	PON feature enabled. 100% duty cycle (PMOS always on) if output voltage drops more than 4%. Increased output ripple in that operation.		
				1	PON feature disabled. Maximum duty cycle = 1 - (tmin_off*fsw)		
				Step down	current force mode		
7	7 buck_dis_curmin 0 R/W	0	current force mode enabled. Inductor current regulated to min 170mA. Higher efficiency in low dropout and low output current operation. Higher output ripple and noise.				
	, back_ais_cainiiii		1	current force mode disabled. Decreased efficiency in low dropout mode and at low output current. Small output ripple and noise.			



7.3 Low Dropout Regulators

The Low Dropout Regulators (LDOs) are linear high performance regulators with programmable output voltages. The LDOs can be controlled by either software (voltage, ON/OFF) or hardware (ON/OFF) using highly configurable GPIO1 to GPIO3 pins.

The Low Dropout Regulators include the following:

- RF and Analog Low Dropout Regulators Described on page 22
- Analog LDO Block Diagram Described on page 22
- SIMCard Low Dropout Regulator Described on page 23
- Low Power Low Dropout Regulator Described on page 24

7.3.1 RF and Analog Low Dropout Regulators

The RF LDOs (VRF_1 - VRF_4) and Analog LDOs (VANA_1 and VANA_2) are designed to supply power to sensitive analog circuits like LNAs, Transceivers, VCOs and other critical RF components of cellular radios. Additionally, these LDOs are suitable for supplying power to audio devices or as a reference for A/D and D/A converters.

The design is optimized to deliver the best compromise between quiescent current and regulator performance for battery powered devices. Stability is guaranteed with ceramic output capacitors (see Figure) of $1\mu F \pm 20\%$ (X5R) or $2.2\mu F + 100 / -50\%$ (Z5U).

The low ESR of these capacitors ensures low output impedance at high frequencies. Regulation performance is excellent even under low dropout conditions, when the power transistor has to operate in linear mode. Power supply rejection is high enough to suppress ripple on the battery caused by the PA in TDMA systems. The low noise performance allows direct connection of noise sensitive circuits without additional filtering networks. The low impedance of the power transistor enables the device to deliver up to 150mA even at nearly discharged batteries without any decrease of performance.

The LDOs have a built-in discharge function when switched off.

Figure 9. Analog LDO Block Diagram

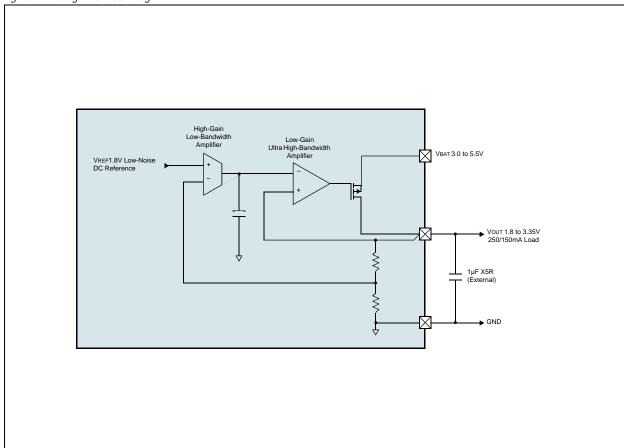




Table 9. RF and Analog LDO Characteristics VBAT = 3.6V; ILOAD = 150mA; $T_A = 25^{\circ}C$; $CLOAD = 2.2\mu F$ (Ceramic); unless otherwise specified.

Symbol	Parameter	Min	Тур	Max	Unit	Notes
VBAT	Supply Voltage Range	3		5.5	V	
Davi	0 0 11			1		VANA_1, VANA_2
Ron	On-Resistance			2	Ω	VRF_1, VRF_2, VRF_3, VRF_4
DCDD	Davier Cumply Delegation Datie	70			٩D	f = 1kHz
PSRR	Power Supply Rejection Ratio	40			dB	f = 100kHz
loff	Shut Down Current			100	nA	
lvdd_ldo	Supply Current			50	μΑ	Without load
Noise	Output Noise		30	50	μVrms	10Hz < f < 100kHz
tstart	Startup Time			200	μs	
Vour	Output Valtage	1.8		2.85	V	VBAT > 3.0V
Vout	Output Voltage	1.8		3.35	V	Full programmable range
Vout_tol	Output Voltage Tolerance	-50		50	mV	
\/, w.=p=0	Line Degulation	-1		1	\/	Static
VLINEREG	Line Regulation	-10		10	mV	Transient; Slope: t _r = 10µs
\/, 0.4.0.0.0.0	Lood Dogulation	-1		1	\/	Static
VLOADREG	Load Regulation	-10		10	mV	Transient; Slope: t _r = 10µs
li is or	Current Limitation	250	400		mA	VANA_1, VANA_2
llimit	Current Limitation	150	180		mA	VRF_1, VRF_2, VRF_3, VRF_4

7.3.2 SIMCard Low Dropout Regulator

The SIMCard LDO (VSIM) is optimized for SIMCard supply. It is designed to achieve the lowest possible power consumption and still provide reasonable regulation characteristics. To ensure high PSRR and stability, a low-ESR ceramic capacitor of 100nF (min.) must be connected to the output. The LDO has a built-in discharge function when switched off.

Table 10. LDO VSIM Characteristics

VBAT = 3.6V; ILOAD = 20mA; T_A = 25°C; CLOAD = 100nF (Ceramic); unless otherwise specified.

Symbol	Parameter	Min	Тур	Max	Unit	Notes
VBAT	Supply Voltage Range	3		5.5	V	
Ron	On-Resistance			50	Ω	
PSRR	Dower Cumply Dejection Datio	40			- dB	f = 1kHz
PSKK	Power Supply Rejection Ratio	20				f = 100kHz
loff	Shut Down Current			100	nA	
IVDD_SIMCARD	Supply Current		40		μΑ	
tstart	Startup Time			200	μs	
Vout	Output Voltage	1.8		3.0	V	VBAT > 3.2V
VOUT_TOL	Output Voltage Tolerance	-50		50	mV	
VLINEREG	Line Demoletien	-10		10	- mV	Static
VLINEREG	Line Regulation	-100		100		Transient; Slope: t _r = 10µs

Table 10. LDO VSIM Characteristics (Continued)

VBAT = 3.6V; ILOAD = 20mA; T_A = 25°C; CLOAD = 100nF (Ceramic); unless otherwise specified.

Symbol	Parameter	Min	Тур	Max	Unit	Notes
VI OADDEG	Load Dogulation	-10		10	ma\/	Static
VLOADREG	Load Regulation	-100		100	mV	Transient; Slope: $t_r = 10\mu s$

7.3.3 Low Power Low Dropout Regulator

The low-power bootstrap LDO (V2_5) is needed to supply power to the core (analog and digital) of the AS3605. LDO V2_5 is designed to achieve the lowest possible power consumption, and still provide reasonable regulation characteristics. LDO V2_5 has two supply inputs selecting automatically the higher one. This gives the possibility to supply the AS3605 core either with the battery or with the Battery Charger, depending on the conditions.

To ensure high PSRR and stability, a low-ESR ceramic capacitor of 1µF (min.) must be connected to the output.

Note: Levelshifters in both directions (input and output) are placed between digital pins (VANA_1) and the digital core (V2_5) of the device, because of the different power supplies.

Table 11. LDO V2_5 Characteristics

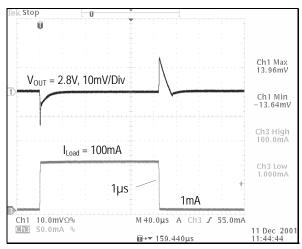
VBAT = 3.6V; CLOAD_EXT = 0; T_A = 25°C; CLOAD = 2.2µF (Ceramic); unless otherwise specified.

Symbol	Parameter	Min	Тур	Max	Unit	Notes
VBAT	Supply Voltage Range	2.8		5.5	V	
VCHARGER	External Charger Adapter voltage	4		15	V	
Ron	On-Resistance		50		Ω	Guaranteed per design
loff	Shut Down Current			100	nA	
lvdd_lpldo	Supply Current			3	μA	Guaranteed per design; consider device internal load for measurement
tstart	Startup Time			200	μs	
Vout	Output Voltage	2.4	2.5	2.6	V	



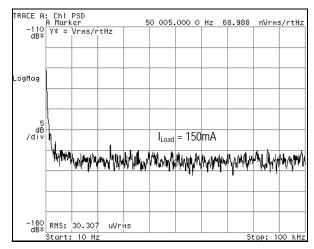
7.3.4 Typical Performance Characteristics

Figure 10. Load Regulation of LDOs VANA_1, VANA_2



X-Axis: 40µs/Div

Figure 11. Output Noise of LDOs VANA_1, VANA_2



Spectral Distribution at 150mA Output Load

Figure 12. Load Regulation of LDO V2_5

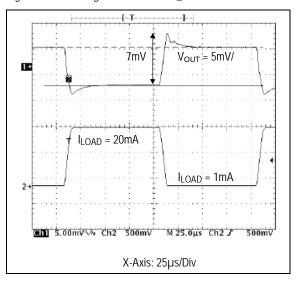
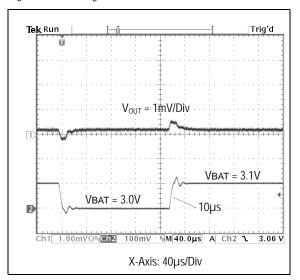


Figure 13. Line Regulation of LDO V2_5





7.3.5 LDO Registers

The Low Dropout Regulators are controlled by the registers listed in Table 12.

Table 12. Low Dropout Regulators Register Summary

Name	Addr.	b7	b6	b5	b4	b3	b2	b1	b0	Page
LDO_RF1 Voltage	02h		-				26			
LDO_RF2 Voltage	03h		-				ldo_rf2_v			27
LDO_RF3 Voltage	04h		-				ldo_rf3_v			27
LDO_RF4 Voltage	05h		-				ldo_rf4_v			27
LDO_ANA2_Voltage	06h		-				ldo_ana2_\	1		27
LDO_ANA1_Voltage	07h		-			ldo_ana1_v				
LDO_SIM_Voltage	08h	-	ldo_sim_v		-					
Reg Power	09h		-	buck_on	ldo_sim_ on	-	-	ldo_ana2 _on	ldo_ana1 _on	28
LDO_GPIO Active	0Fh	-	-	ldo_rf4_g pio	ldo_rf3_g pio	ldo_rf2_g pio	ldo_rf1_g pio	ldo_ana2 _gpio	ldo_buck _gpio	29
LDO_CHG	10h	ldo_rf4 _on			ldo_rf1		ana1_sw	29		
LDO_AD GPIOx	11h		-			ldo_ana2_gpio_sel buck_gpio_sel				
LDO_RF GPIOx	12h	ldo_rf4	_gpio_sel	ldo_rf3_	_gpio_sel Ido_rf2_gpio_sel Ido_rf1_gpio_sel					31

LDO_RF1 Voltage Register (Address 02h).

Addr: 02h			ge			
Addi. Uzii		Sets the voltage	for LDO VRF_1.			
Bit	Bit Name	Default	Access	Access Bit Description		
				00000	1.8V	
4:0	ldo_rf1_v	Boot ROM	R/W		(LSB = 50mV)	
				11111	3.35V	
7:5	-	NA	NA			



LDO_RF2 Voltage Register (Address 03h).

Addr: 03h						
Auur. USII	Sets the voltage for LDO VRF_2.					
Bit	Bit Name	Default	Access	Bit Description		
				00000	1.8V	
4:0	ldo_rf2_v	Boot ROM	R/W		(LSB = 50mV)	
				11111	3.35V	
7:5	-	NA	NA			

LDO_RF3 Voltage Register (Address 04h).

Addr: 04h		LDO_RF3 Voltage					
Sets the voltage for LDO VRF_3.			for LDO VRF_3.				
Bit	Bit Name	Default	Access	Bit Description			
				00000	1.8V		
4:0	ldo_rf3_v	Boot ROM	R/W		(LSB = 50mV)		
				11111	3.35V		
7:5	-	NA	NA				

LDO_RF4 Voltage Register (Address 05h).

Addr: 05h		LDO_RF4 Volta	DO_RF4 Voltage					
Addi. 0311		Sets the voltage	for LDO VRF_4.					
Bit	Bit Name	Default	Access	Access Bit Description				
				00000	1.8V			
4:0	ldo_rf4_v	Boot ROM	R/W		(LSB = 50mV)			
				11111	3.35V			
7:5	-	NA	NA					

LDO_ANA2_Voltage Register (Address 06h).

Addr: 06h		LDO_ANA2_Vo	LDO_ANA2_Voltage					
Addi. 00i		Sets the voltage	for LDO VANA_2	2.				
Bit	Bit Name	Default	It Access Bit Description					
				Sets the vol	tage for LDO VANA_2			
4.0	ب د میرو	D I DOM	DAM	00000	1.80V			
4:0	ldo_ana2_v	Boot ROM	R/W		(LSB = 50mV)			
				11111	3.35V			
7:5	-	NA	NA					



LDO_ANA1_Voltage Register (Address 07h).

Addr: 07h	Addr: 07h				
Auui. 071		Sets the voltage	for LDO VANA_1	l.	
Bit	Bit Name	Default	Access Bit Description		
				Sets the voltage for LDO VANA_1	
4.0	ldo opo1 v	D+ DOM	DW	00000	1.8V
4:0	ldo_ana1_v	Boot ROM	R/W		(LSB = 50mV)
				11111	3.35V
7:5	-	NA	NA		

LDO_SIM_Voltage Register (Address 08h).

Addr: 00h	Addr: 08h					
Auui. voii		Sets the voltage	for Digital LDO V	/SIM.		
Bit	Bit Name	Default	Access	Bit Description		
5:0	-	NA	NA			
				Sets the vo	oltage for LDO VSIM.	
6	ldo_sim_v	Boot ROM	R/W	0	1.8V	
				1	3.0V	
7	-	NA	NA			

Reg Power Register (Address 09h).

۸ dds,00b		Reg Power						
Addr:09h		Enables/disables	s voltage regulat	tors.	ors.			
Bit	Bit Name	Default	Access	Bit Descr	iption			
				Enables control of LDO VANA_1.				
0	ldo_ana1_on	Boot ROM	R/W		o not set this bit = 0 or serial interface access will be disabled.			
		2001110		0	LDO VANA_1 is OFF.			
				1	LDO VANA_1 is ON.			
				Enables c	ontrol of LDO VANA_2.			
1	ldo_ana2_on	Boot ROM	R/W	0	LDO VANA_2 is OFF.			
				1	LDO VANA_2 is ON.			
3:2	-	NA	NA					
				Enables c	ontrol of LDO VSIM.			
4	ldo_sim_on	Boot ROM	R/W	0	LDO VSIM is OFF.			
				1	LDO VSIM is ON.			
				Enables th	ne Step Down DC/DC Converter.			
5	buck_on	Boot ROM		0	Step Down DC/DC Converter is OFF.			
				1	Step Down DC/DC Converter is ON.			
7:6	-	NA	NA					



LDO_GPIO Active Register (Address 0Fh).

Addr: 0F	'h	LDO_GPIO Active						
Auui. Ur	11	Activates 0	GPIO ON/OF	F control	for voltage regulators.			
Bit	Bit Name	Default	Access	Bit Description				
				Activate	s GPIO control of Step Down DC/DC Converter.			
0	buck_gpio	Boot ROM	R/W	0	Controlled by software.			
		T(OW)		1	On when assigned GPIO pin = 1 and bit buck_on = 1.			
				Activate	s GPIO control for LDO VANA_2.			
1	ldo_ana2_gpio	Boot ROM	R/W	0	Controlled by software.			
		T(OW)		1	On when assigned GPIO pin = 1 and bit Ido_ana2_on = 1.			
						Activates GPIO control for LDO VRF_1.		
2	ldo_rf1_gpio	Boot ROM	R/W	0	Controlled by software.			
		T(OW)		1	On when assigned GPIO pin = 1 and bit Ido_rf1_on = 1.			
				Activate	s GPIO control for LDO VRF_2.			
3	ldo_rf2_gpio	Boot ROM	R/W	0	Controlled by software.			
				1	On when assigned GPIO pin = 1 and bit Ido_rf2_on = 1.			
				Activate	s GPIO control for LDO VRF_3.			
4	ldo_rf3_gpio	Boot ROM	R/W	0	Controlled by software.			
		1.0		1	On when assigned GPIO pin = 1 and bit Ido_rf3_on = 1.			
				Activate	s GPIO control for LDO VRF_4.			
5	ldo_rf4_gpio	Boot ROM	R/W	0	Controlled by software.			
		1.0.01		1	LDO VRF_4 is on when assigned GPIO pin = 1 and bit Ido_rf4_on = 1.			
7:6	-	NA	NA					

LDO_RF Switch Register (Address 10h).

Addr: 10h		LDO_CHG						
Addi. 101	Enables LDOs and high-side swite		d high-side switch	nes.				
Bit	Bit Name	Default	Access	Bit Descrip	tion			
				0	VANA_1 operates as LDO.			
0	ana1_sw	0	R/W	1	VANA_1 is operating as high-side switch (Ron=1 Ω); valid if Ido_ana1_on = 0.			
				0	VANA_2 operates as LDO.			
1	ana2_sw	0	R/W	1	VANA_2 is operating as high-side switch (RoN=1 Ω); valid if Ido_ana2_on = 0.			
				Enables cor	ntrol of LDO VRF_1.			
4	ldo_rf1_on	0	R/W	R/W	R/W	0	LDO VRF_1 is OFF.	
				1	LDO VRF_1 is ON.			



30 - 73

Addr: 10h		LDO_CHG						
Addi. 1011		Enables LDOs and high-side switches.						
Bit	Bit Name	Default	Access	Bit Descript	ion			
				Enables con	trol of LDO VRF_2.			
5	5 ldo_rf2_on	0	R/W	0	LDO VRF_2 is OFF.			
				1	LDO VRF_2 is ON.			
			R/W	Enables control of LDO VRF_3.				
6	ldo_rf3_on	0		0	LDO VRF_3 is OFF.			
				1	LDO VRF_3 is ON.			
		0	R/W	Enables con	trol of LDO VRF_4.			
7	ldo_rf4_on			0	LDO VRF_4 is OFF.			
				1	LDO VRF_4 is ON.			

Ido_anax_on*	anax_sw*	ANA LDO Function				
0	0	OFF				
0	1	Fully ON, Ron = 1Ω				
1	0	Linear Voltage Regulator				
1	1	Not Allowed				

^{*} Where *x* = 1-4

LDO_AD GPIOx Register (Address 11h).

Addr. 11k	Addr: 11h		LDO_AD GPIOx						
Addi. III			Selects GPIO pin for power ON/OFF control for DCDC and VANA_2.						
Bit	Bit Name	Default	Access	Bit Descri	ption				
				Valid if GF	PIO activation bit buck_gpio = 1				
				00	GPI01				
1:0	buck_gpio_sel	00 _h	R/W	01	GPIO2				
				10	GPIO3				
				11	Do not use this setting				
				Valid if GPIO activation bit Ido_ana2_gpio = 1					
			R/W	00	GPI01				
3:2	ldo_ana2_gpio_sel	00 _h		01	GPIO2				
				10	GPIO3				
				11	Do not use this setting				
7:4	NA								



LDO_RF GPIOx Register (Address 12h).

Addr: 12h		LDO_RF GPIOx						
Auui. 1211		Selects GPIO pin for power ON/OFF control for RF LDOs VRF_1 - VRF_4.						
Bit	Bit Name	Default	Access	Bit Descri	iption			
				Valid if Idc	o_rf1_gpio = 1			
				00	GPIO1			
1:0	ldo_rf1_gpio_sel	Boot ROM	R/W	01	GPIO2			
				10	GPIO3			
				11	Do not use this setting			
				Valid if Ido	o_rf2_gpio = 1			
		Boot ROM	R/W	00	GPIO1			
3:2	ldo_rf2_gpio_sel			01	GPIO2			
				10	GPIO3			
				11	Do not use this setting			
				Valid if Ido				
				00	GPIO1			
5:4	ldo_rf3_gpio_sel	Boot ROM	R/W	01	GPIO2			
				10	GPIO3			
				11	Do not use this setting			
				Valid if Ido				
				00	GPI01			
7:6	ldo_rf4_gpio_sel	Boot ROM	R/W	01	GPIO2			
				10	GPIO3			
				11	Do not use this setting			



7.4 Charge Pump

The Charge Pump uses the external flying capacitor C2 (470nF) to generate output voltages higher than the battery voltage. There are two different operating modes of the charge pump itself:

- 1:1 Bypass Mode
 - Battery input and output are connected by a low-impedance switch
 - Battery current = output current
- 1:2 Mode
 - The output voltage is up to 2 times the battery voltage (without load), but is limited to VCPOUTmax all the time
 - Battery current = 2 times output current

As the battery voltage decreases, the Charge Pump must be switched from 1:1 mode to 1:2 mode in order to provide enough supply for the current sinks. Depending on the actual current, the mode with best overall efficiency can be automatically or manually selected:

The charge pump mode switching can be done manually or automatically with the following possible software settings:

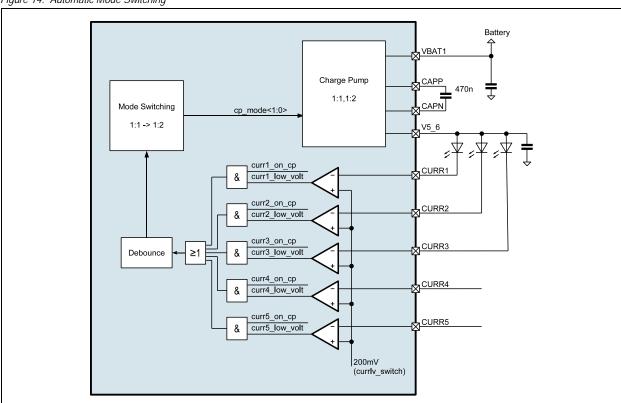
- Automatic
 - Start with 1:1 mode
 - Switch up automatically to 1:2 mode
- Manual
 - Set modes 1:1 and 1:2 by software

7.4.1 Charge Pump Mode Switching

If automatic mode switching is enabled (**cp_mode_switching** = 0) the charge pump monitors the current sinks, which are connected via a LED to the output V5_6. To identify these current sources (sinks), the registers CP mode Switch (register bits **curr1_on_cp** ...**curr5_on_cp**) should be setup before starting the charge pump (**cp_on** =1). If any of the voltage on these current sources drops below the threshold (currlv_switch, currhv_switch), the 1:2 mode is selected after the debounce time. The CP will not switch back to 1:1 mode.

If the currX_on_cp=0 and the according current sink is connected to the charge pump, the current sink will be functional, but there is no up switching of the charge pump, if the voltage compliance is too low for the current sink to supply the specified current.

Figure 14. Automatic Mode Switching





The Charge Pump requires the external components specified in Table 13.

Table 13. Charge Pump External Components

Symbol Parameter		Min	Тур	Max	Unit	Notes
CFLY (C2)	External Flying Capacitor		470		nF	Ceramic low-ESR capacitor between pins CAPP and CAPN (see page 2).
CSTORE (C3)	External Storage Capacitor	1		4.7	μF	Ceramic low-ESR capacitor between pins V5_6 and VSS (see page 2).

Note: Connections to the two external capacitors should be kept as short as possible.

Table 14. Charge Pump Parameters

VBAT = 3.6V; T_{AMB} = 25°C; unless otherwise specified.

Symbol	Parameter	Min	Тур	Max	Unit	Notes
ICPOUT	Output Current	0		60	mA	
VCPOUTmax	Output Voltage			5.6	V	including output ripple
Don	Effective Charge Pump Output		8.8		Ω	VBAT = 3.0V, cp_mode[1:0] = 1:1
R _{CP}	Resistance		31		Ω	VBAT = 3.0V, cp_mode[1:0] = 1:2
currlv_switch	if the current sink voltage drops below this threshold it will change from 1:1 to 1:2 mode			200	mV	cp_mode_switching = automatic
+	start up dahaunaa tima		240		110	cp_start_debounce = 0
t _{deb}	start_up debounce time		2000		μs	cp_start_debounce = 1
ISHUTDOWN	Shutdown Current			0.1	μΑ	

7.4.2 Charge Pump Registers

Table 15. Charge Pump Register Summary

Name	Addr.	b7	b6	b5	b4	b3	b2	b1	b0	Page
Charge Pump Control Onkey Pulldown	18h	cp_auto_ on	cp_start_d ebounce	onkey_pul ld_off	cp_freq	cp_mode _switchin g	cp_mo	de[1:0]	cp_on	34
CP Mode Switch	36h		NA		curr5_on _cp	curr4_on _cp	curr3_on_ cp	curr2_on_ cp	curr1_on_ cp	35
Curr Low Voltage Status	37h		NA		curr5_low _volt	curr4_low _volt	curr3_low _volt	curr2_low _volt	curr1_low _volt	35



Charge Pump Control Onkey Pulldown Register (Address 18h).

Addr: 18h		Charge Pump Control Onkey Pulldown							
Addr: 18n		Sets the operation	on mode of the (Charge Pum	harge Pump.				
Bit	Bit Name	Default	Access	Bit Desc	ription				
0	cp_on	0b	R/W	0	Set CP into 1:1 mode (OFF state) unless cp_auto_on is set.				
	·			1	Enable manual mode switching				
					e (in manual mode sets this mode, in automatic mode reports al mode used)				
				00	1:1 mode				
2:1	cp_mode[1:0]	00b	R/W	01	- 1:1 mode				
				10	1.2				
				11	1:2 mode				
		Ob	R/W	Set the m	node switching algorithm				
3	cp_mode_switching			0	Automatic mode switching				
3				1	Manual mode switching; register cp_mode[1:0] defines the actual CP mode used.				
				Clock fre	quency selection				
4	cp_freq	0b	R/W	0	1 MHz				
				1	500 kHz				
г	onkov nulld off	Ob	DW	0	pull down on ON-key active				
5	onkey_pulld_off	0b	R/W	1	pull down on ON-key deactivated				
				0	Mode switching debounce timer is always 240µs.				
6	cp_start_debounce	0b	R/W	1	Upon startup (cp_on set to 1) the mode switching debounce time is first started with 2ms then reduced to 240µs.				
				0	The CP is swiched ON/OFF with cp_on				
7	cp_auto_on	1b	R/W	1	The CP is automatically switched on if a current sink, which is connected to the CP (defined by registers CP Mode Switch 1&2) is switched ON and detects a low voltage condition.				



CP Mode Switch Register (Address 36h).

Addr: 36h		CP Mode Switch							
			Setup which current sinks are connected (via LEDs) to the CP; if set to 1 the corresponding current sink is used for automatic mode selection of the CP.						
Bit	Bit Name	Default	Access	Bit Desc	ription				
0	curr1 on on	Oh	R/W	0	Current sink CURR1 is not connected to the CP				
0	curr1_on_cp	0b		1	Current sink CURR1 is connected to the CP				
1	1 curr2_on_cp	Oh	R/W	0	Current sink CURR2 is not connected to the CP				
'		0b		1	Current sink CURR2 is connected to the CP				
2	ourr? on on	Oh	R/W	0	Current sink CURR3 is not connected to the CP				
2	curr3_on_cp	0b		1	Current sink CURR3 is connected to the CP				
2	ourr4 on on	Ol-	R/W	0	Current sink CURR4 is not connected to the CP				
3	curr4_on_cp	0b		1	Current sink CURR4 is connected to the CP				
4	ourrE on on	Oh	R/W	0	Current sink CURR5 is not connected to the CP				
4	curr5_on_cp	0b		1	Current sink CURR5 is connected to the CP				
5:7	-	NA	NA						

Curr Low Voltage Status Register (Address 37h).

		Curr Low Voltage Status						
Addr: 37h		Indicates the low voltage status of the current sinks. If the currX_low_v bit is set, the voltage on the current sink is too low, to drive the selected output current.						
Bit	Bit Name	Default	Access	Bit Descr	iption			
0	ourr1 love v	NA	R	0	The voltage of current sink CURR1 > currlv_switch			
0	curr1_low_v	IVA	K	1	The voltage of current sink CURR1 < currlv_switch			
1	1 curr2_low_v	NA	R	0	The voltage of current sink CURR2 > currlv_switch			
l I				1	The voltage of current sink CURR2 < currlv_switch			
2	aurra laur u	NIA.	R	0	The voltage of current sink CURR3 > currlv_switch			
2	curr3_low_v	NA		1	The voltage of current sink CURR3 < currlv_switch			
3	ourr4 love v	NΙΛ	R	0	The voltage of current sink CURR4 > currlv_switch			
3	curr4_low_v	NA	K	1	The voltage of current sink CURR4 < currlv_switch			
4	ourrE low v		D	0	The voltage of current sink CURR5 > currlv_switch			
4	4 curr5_low_v	NA	R	1	The voltage of current sink CURR5 < currlv_switch			
5:7	-	NA	NA					



7.5 General Purpose Input/Output

The general purpose input/output pins (GPIO1 - GPIO3) are highly configurable and independently controlled.

Table 16. DC Characteristics Input/Output Pin with Selectable Supply GPIO1:GPIO3

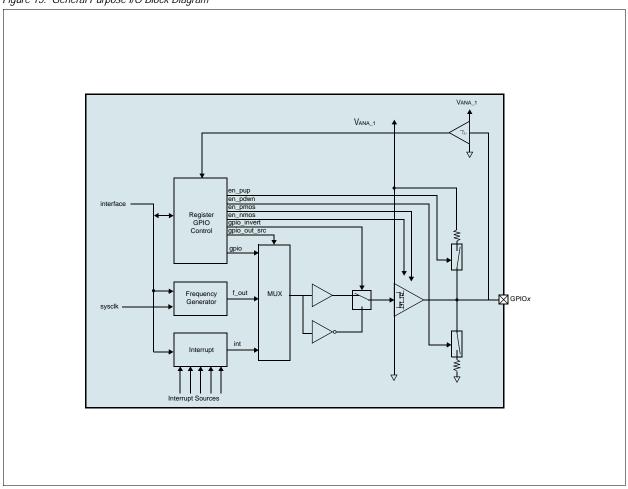
Symbol	Parameter	Min	Max	Unit	Notes
VIH	High-Level Input Voltage	0.7 x Vana_1		V	
VIL	Low-Level Input Voltage		0.3 x Vana_1	V	
İLEAK	Input Leakage Current (if not used as pulldown/pullup)	-5	5	μΑ	to VANA_1 and VSS
IPULLDOWN	Pulldown Current (if configured as pulldown)	5	50	μΑ	to VSS
lpullup	Pullup Current (if configured as pullup)	-200	-20	μΑ	to V5_6 or VANA_1 as configured
Voн	High-Level Output Voltage Supply VANA_1	0.8 x VANA_1		V	at -2mA
Vol	Low-Level Output Voltage		0.2 x VANA_1	V	at 2mA
CLOAD	Capacitive Load		50	pF	

GPIO1 - GPIO3 can be used to accommodate the following functionality:

- Software controlled input and output
- Input pin for the Watchdog
- Signal input (GPIO1-GPIO3)
- Interrupt output with configurable interrupt source
- Configurable frequency and duty cycle output
- External clock input for Step Up/Down DC/DC Converters and Charge Pump synchronization (GPIO1 only)
- Active pullup or pulldown; can be combined with other I/O functions
- Output open drain (push or pull type)



Figure 15. General Purpose I/O Block Diagram



7.5.1 GPIO Registers

GPIO1 - GPIO3 are controlled by the registers listed in Table 17.

Table 17. GPIO Register Summary

Name	Addr.	b7	b6	b5	b4	b3	b2	b1	b0	Page
GPIO1 Control	1Ah	gpio1_	gpio1_out_src gpio1_ invert			gpio1_pulls gpio1_ gpio			_mode	38
GPIO2 Control	1Bh	gpio2_	_out_src	gpio2_ invert	gpio2	_pulls	gpio2_low _curr	gpio2	_mode	38
GPIO3 Control	1Ch	gpio3_	gpio3_out_src gpio3_ gpio3_pulls gpio3_ gpio3_m					_mode	39	
GPIO Signal	21h		- gpio3 gpio2 gpio1						40	
GPIO Frequency Control High Time	22h				gpio_l	h_time				41
GPIO Frequency Control Low Time	23h				gpio_	I_time				41
Clock Generation	1Eh				-				ext_clk	41
Interrupt Enable	1Fh	chgov_in t_en	chgrmv_in t_en					wdog _int_en	42	
Interrupt Status	20h	chgov_i	chgrmv_i	resume_i	chdet_i	onkey_i	ovtmp_i	vchoff_i	wdog_i	43



GPIO1 Control Register (Address 1Ah).

Addr: 1Al	h	GPIO1 Control						
Addi: TAI	n	Configures pin (GPI01.					
Bit	Bit Name	Default	Access	Bit Descr	iption			
				Sets the direction for pin GPIO1.				
				00	Input only			
1:0	gpio1_mode	00	R/W	01	Output (push and pull)			
				10	Output (open drain, only push; only NMOS is active)			
				11	Output (open drain, only pull; only PMOS is active)			
		0	DAM	0	Fast output slew rate			
2	gpio1_low_curr		R/W	1	Slow output slew rate			
	4.2	00	R/W	Sets pullup/pulldown to pin GPIO1 (independent of bit gpio1_mode setting).				
4:3				00	None			
4.3	gpio1_pulls			01	Pulldown			
				10	Pullup			
				11	NA			
				0	Output signal is not inverted.			
5	gpio1_invert	0	R/W	1	Inverts any output signal going to GPIO1. This is useful for the Watchdog output source to make the output active high or low.			
				Sets the s	ource of pin GPIO1 output.			
				х0	Bit gpio1 controlled through the serial interface.			
7:6	gpio1_out_src	rc 00	R/W	01	Frequency generator defined by bits gpio_h_time and gpio_l_time .			
				11	Interrupt signal (see Interrupt Function on page 42).			

GPIO2 Control Register (Address 1Bh).

Addr: 1Bl	h	GPIO2 Control					
Auui. Ibi	ı	Configures pin GPIO2.					
Bit	Bit Name	Default	Access	Bit Description			
				Sets the dir	rection for pin GPIO2.		
		00	R/W	00	Input only		
1:0	gpio2_mode			01	Output (push and pull)		
				10	Output (open drain, only push; only NMOS is active)		
				11	Output (open drain, only pull; only PMOS is active)		
2		0	5.44	0	Fast output slew rate		
2	2 gpio2_low_curr		R/W	1	Slow output slew rate		



Addr: 1Bl	•	GPIO2 Control						
Auui. Ibi	1	Configures pin GPIO2.						
Bit	Bit Name	Default	Access	Bit Descrip	ption			
				Sets pullup setting).	/pulldown to pin GPIO2 (independent of bit gpio2_mode			
				00	None			
4:3	gpio2_pulls	00	R/W	01	Pulldown			
				10	Pullup			
				11	NA			
				0	Output signal is not inverted.			
5	gpio2_invert	0	R/W	1	Inverts any output signal going to pin GPIO2. This is useful for the Watchdog output source to make the output active high or low.			
				Sets the so	ource of pin GPIO2 output.			
				х0	Bit gpio2 (controlled through the serial interface).			
7:6	gpio2_out_src	00	R/W	01	Frequency generator defined by bits gpio_h_time and gpio_l_time .			
				11	Interrupt signal (see Interrupt Function on page 42).			

GPIO3 Control Register (Address 1Ch).

Addr. 10k	Addr: 1Ch		GPIO3 Control					
Addi. ICII		Configures pin GPIO3.						
Bit	Bit Name	Default	Access	Bit Description				
				Sets the di	irection for pin GPIO3.			
		00	R/W	00	Input only.			
1:0	gpio3_mode			01	Output (push and pull).			
				10	Output (open drain, only push; only NMOS is active).			
				11	Output (open drain, only pull; only PMOS is active).			
2.2	0 0	DAM	0	Fast output slew rate				
3:2	3:2 gpio3_low_curr		R/W	1	Slow output slew rate			



Addr. 10k	•	GPIO3 Control						
Addr: 1Ch	1	Configures pin GPIO3.						
Bit	Bit Name	Default	Access	Bit Descri	ption			
				Sets pullup setting).	o/pulldown to pin GPIO3 (independent of bit gpio3_mode			
				00	None			
4	gpio3_pulls	00	R/W	01	Pulldown			
				10	Pullup			
				11	NA			
				0	Output signal is not inverted.			
5	gpio3_invert	0	R/W	1	Inverts any output signal going to pin GPIO3. This is useful for the Watchdog output source to make the output active high or low.			
				Sets the so	ource of pin GPIO3.			
				х0	Bit gpio3 (controlled through the serial interface)			
7:6	gpio3_out_src	00	R/W	01	Frequency generator defined by bits gpio_h_time and gpio_l_time .			
			11	Interrupt signal (see Interrupt Function on page 42).				

GPIO Signal Register (Address 21h).

Table 18. GPIO Signal Register (Address 33)

Addr: 21h		GPIO Signal						
Auui. Ziii		Reads the logic	Reads the logic signal of the GPIO pins, independently of any other GPIO bit setting.					
Bit	Bit Name	Default	Access	Bit Description				
0	gpio1	NA	R	Reads the logic signal from pin GPIO1. If gpio1_out_src = 00, this is the output signal at pin GPIO1.				
1	gpio2	NA	R	Reads the logic signal from pin GPIO2. If gpio2_out_src = 00, this is the output signal at pin GPIO2.				
2	gpio3	NA	R	Reads the logic signal from pin GPIO3. If gpio3_out_src = 00, this is the output signal at pin GPIO3.				
7:3	-	NA	NA					



7.5.2 Programmable Frequency Generator

The Programmable Frequency Generator is controlled by bits **gpio_h_time** and **gpio_l_time**. It generates a waveform with 0.9 microseconds times **gpio_h_time** high-level and 0.9 microseconds times **gpio_l_time** low-level. The accuracy of these timings is ±10%.

The frequency of the Programmable Frequency Generator is:

(EQ 1)

Where:

 $tclk = 1/fclk = 1/1.1MHz (typ) = 0.909\mu s (typ)$

The purpose of the Programmable Frequency Generator is to have a controlled sweepable frequency or duty cycle source for one of the following:

- General User-Defined Clock
- 8-Bit DAC (output should be filtered by an RC filter)
- (High) Positive and Negative Voltage Generation (see Interrupt Function on page 42)

7.5.3 Programmable Frequency Generator Registers

Bit definition for programmable frequency generator registers are given below.

GPIO Frequency Control High Time Register (Address 22h).

Addr: 22h		GPIO Frequency Control High Time					
Configures programmable frequency			grammable frequ	uency generato	r.		
Bit	Bit Name	Default	Access	Bit Description			
	7:0 gpio_h_time 00 _h R/W			Defines the nu programmable	umber of system clock cycles (typ 0.9µs), that the e frequency generator at the GPIO output(s) is high.		
7:0		R/W	00 _h	0.909µs			
				FF _h 232.7μs			

GPIO Frequency Control Low Time Register (Address 23h).

Addr: 23h			cy Control Low	w Time		
Configures programmable frequency			grammable frequ	uency generato	r.	
Bit	Bit Name	Default	Access	Bit Description		
				Defines the no programmable	umber of system clock cycles (typ 0.9µs), that the e frequency generator at the GPIO output(s) is low.	
7:0	gpio_l_time	64 _h R/W	00 _h 0.909μs			
			FFh	232.7µs		



7.5.4 Interrupt Function

Any of the GPIO pins (GPIO1 - GPIO3) can be configured as interrupt output pins. To enable this function, the corresponding GPIO control bits must be set to 11b. See **gpio1_out_src**, **gpio2_out_src**, or **gpio3_out_src**.

Several signals can be configured as interrupt source using the Interrupt Enable (page 42). A rising edge of an enabled interrupt control signal sets the selected GPIO interrupt output pin = 1.

The Interrupt Status (page 43) shows the currently active interrupt signals. Reading this register resets the Interrupt Status (page 43) bits and sets the active GPIO pin (GPIO 1 - GPIO3) = 0.

7.5.5 Interrupt Registers

Bit definition for Interrupt registers are given below.

Interrupt Enable Register (Address 1Fh).

Addr: 1		Interrupt Enab	Interrupt Enable						
Addi: II	rn	Enables/disables interrupt sources.							
Bit	Bit Name	Default	Access		Bit Description				
0	wdog_int_en	0	R/W	0	Disables watchdog alarm as interrupt source signal.				
0	wdog_ini_en	U	K/VV	1	Enables watchdog alarm as interrupt source signal.				
1	vchoff int on	1	R/W	0	Disables charge termination voltage as interrupt source signal.				
I	vchoff_int_en	l	K/VV	1	Enables charge termination voltage as interrupt source signal.				
2	outmo int on	1	1 R/W -	0	Disables ov_temp_110 (device temperature alert at 110°C).				
2	ovtmp_int_en	l		1	Enables ov_temp_110 (device temperature alert at 110°C).				
2	ankov int an	1	DAM	0	Disables pin ON (active high).				
3	onkey_int_en	l	R/W	1	Enables pin ON (active high).				
4	chdot int on	1	DAM	0	Disables charger detection.				
4	chdet_int_en	l	R/W	1	Enables charger detection.				
-	rocumo int on	1	DAM	0	Disables charger-resume interrupt.				
5	resume_int_en	l	R/W	1	Enables charger-resume interrupt.				
,	obarmy int on	1	DAM	0	Disables charger-removed interrupt.				
6	chgrmv_int_en		R/W	1	Enables charger-removed interrupt.				
7	chaou int co	1	DAM	0	Disables charger overvoltage interrupt.				
/	chgov_int_en 1 R/W	K/VV	1	Enables charger overvoltage interrupt.					



Interrupt Status Register (Address 20h).

Addr: 20)h	Interrupt Statu	IS				
Auui. 20	л	Displays the status of the interrupt inputs.					
Bit	Bit Name	Default	Access	Bit Desc	Bit Description		
	udoa i	0	R	0	Software or hardware watchdog is OFF or has not rolled over.		
0	wdog_i	0	K	1	Software or hardware watchdog is rollover.		
1	voboff i	0	R	0	Battery voltage is below VCHOFF (see page 12) threshold.		
ļ ļ	vchoff_i	0	K	1	Battery voltage has reached VCHOFF threshold.		
2	ovtmn i	0 0	0	Device temperature is below 110°C.			
2	ovtmp_i	0	R	1	110°C temperature threshold ov_temp_110 has been reached.		
3	onkov i	0	R	0	ON key has not been pressed.		
3	onkey_i	0	K	1	ON key has been pressed (rising edge).		
4	chdet_i	0	R	Charger	detection interrupt, active if ChDet is falling.		
5	resume_i	0	R	Active if \	Active if VRESUME is reached (see Table 5).		
6	chgrmv_i	0	R	Charger	Charger detection interrupt, active if ChDet is falling.		
7	chgov_i	0	R	Charger of	Charger over voltage interrupt, active if ChOv is rising.		



44 - 73

7.6 Current Sinks

The AS3605 contains 5 general purpose current sinks intended to control backlights, buzzers, and vibrators. All current sinks have an integrated protection (VPROTECT) against overvoltage and can therefore also drive inductive loads. The current sinks can also be used as switches to VSS with configurable impedance as indicated in Table 19.

Table 19. Current Source Characteristics

Symbol	Parameter	Min	Тур	Max	Unit	Notes
lcurr <i>x</i>	curr1_current = 01 _h - FF _h curr2_current = 01 _h - FF _h	0.63		160	mA	resolution = 0.6275mA
lcurr <i>x</i>	curr3_current = 01 _h - FF _h curr4_current = 01 _h - FF _h curr5_current = 01 _h - FF _h	0.16		40	mA	resolution = 0.1569mA
VPROTECT	Maximum voltage at pin CURRx to protect driver transistor			VBAT + 2.0V	V	ISINK ≥ 20mA, guaranteed by design

Note: If a voltage higher than VPROTECT is applied to pins CURR1 - CURR5, a current of more than 20mA will flow into the AS3605. This protects the device from voltage rises caused by inductive loads.

7.6.1 Current Sink Registers

The current sinks are controlled by the registers listed in Table 20.

Table 20. Current Sink Register Summary

Name	Addr.	b7	b6	b5	b4	b3	b2	b1	b0	Page
CURR5 Control GPIO Map	19h		- curr5_gpio curr5_ctrl				45			
CURR1 Value	24h		curr1_current							45
CURR2 Value	25h		curr2_current						45	
CURR3 Value	26h		curr3_current						46	
CURR4 Value	27h				curr4_	current				46
CURR Control	28h	curr	curr4_ctrl curr3_ctrl curr2_ctrl curr1_ctrl					46		
CURR5 Value	29h	curr5_current						47		
CURR GPIO Map	2Ah	curr4	_gpio	curr3	3_gpio	curr2	_gpio	curr1	_gpio	47

Note: For all current sinks, the currx_on signal is controlled with the currx_ctrl bits.



CURR5 Control GPIO Map Register (Address 19h).

Addr: 19h		CURR5 Control GPIO Map					
Addi. 191							
Bit	Bit Name	Default	Access	Bit Descri	ption		
				00	Pin CURR5 is turned OFF		
1:0	curr5_ctrl	curr5_ctrl 00b	R/W	01	Pin CURR5 is active		
				1x	GPIO control; pin is active when curr5_gpio = 1		
			R/W		curr5_ctrl = 1x, the following pin is assigned for turning the n ON and OFF.		
				00	GPIO1		
3:2	curr5_gpio	00b		01	GPIO2		
				10	GPIO3		
			11	NA			
7:4	-	NA	NA				

CURR1 Value Register (Address 24h).

Addr: 24h		CURR1 Value					
Addr: 24n		Sets the current / resistance of current source CURR1.					
Bit	Bit Name	Default	Access	Bit Description			
		00 _h	R/W	00 _h	Power Down		
7.0	curr1 current			01 _h	0.6275mA		
7:0	7:0 curr1_current						
				FFh	160mA		

CURR2 Value Register (Address 25h).

Addr: 25h		CURR2 Value					
Addi: 25fi		Sets the current / resistance of current source CURR2.					
Bit	Bit Name	Default	Access	Bit Description			
		00 _h	R/W	00 _h	Power Down		
7:0	curr2 current			01 _h	0.6275mA		
7.0	7:0 curz_current						
				FF _h	160mA		



CURR3 Value Register (Address 26h).

Addr: 26h		CURR3 Value					
Addr: 201		Sets the current / resistance of current source CURR3.					
Bit	Bit Name	Default	Access	Bit Description			
		00 _h	R/W	00 _h	Power Down		
7.0	curr? current			01 _h	0.1569mA		
7:0	7:0 curr3_current						
			FF _h	40mA			

CURR4 Value Register (Address 27h).

Addr: 27h		CURR4 Value					
Addr: 2/n		Sets the current	CURR4.				
Bit	Bit Name	Default	Access	Bit Description			
		00 _h	R/W	00 _h	Power Down		
7.0	curr4 current			01 _h	0.1569mA		
7.0	7:0 curr4_current						
			FF _h	40mA			

CURR Control Register (Address 28h).

Addr: 28h		CURR Control						
Auui. Zoii		Selects software/ hardware control of current sources.						
Bit	Bit Name	Default	Access	Bit Description				
					Pin CURR1 is turned OFF.			
1:0	curr1_ctrl	00b	R/W	01	Pin CURR1 is active.			
			1 <i>x</i>	GPIO control; pin is active when curr1_gpio =1.				
			00	Pin CURR2 is turned OFF.				
3:2 curr2_ctrl	curr2_ctrl	00b	R/W	01	Pin CURR2 is active.			
				1 <i>x</i>	GPIO control; pin is active when curr2_gpio =1.			
				00	Pin CURR3 is turned OFF.			
5:4	curr3_ctrl	00b	R/W	01	Pin CURR3 is active.			
				1 <i>x</i>	GPIO control; pin is active when curr3_gpio = 1.			
				00	Pin CURR4 is turned OFF.			
7:6	curr4_ctrl	00b	R/W	01	Pin CURR4 is active.			
				1 <i>x</i>	GPIO control; pin is active when curr4_gpio = 1.			



CURR5 Value Register (Address 29h).

Addr: 29h		CURR5 Value					
Auui. 231		Sets the current.					
Bit	Bit Name	Default	Default Access Bit Description				
		00 _h	R/W	00 _h	Power Down		
7.0	currE current			01 _h	0.1569mA		
7:0	7:0 curr5_current						
				FFh	40mA		

CURR GPIO Map Register (Address 2Ah).

Addr: 2Al	h .	CURR GPIO Map						
Auui: ZAI		Selects GPIO pii	n to control curr	ent sources.				
Bit	Bit Name	Default	Access	Bit Description				
				If bits curr1_ctrl = 1 <i>x</i> , the following pin is assigned for turning the CURR1 pin ON and OFF.				
				00	GPIO1			
1:0	curr1_gpio	00	R/W	01	GPIO2			
				10	GPIO3			
		11	NA					
					P_ctrl = 1 <i>x</i> , the following pin is assigned for turning the ON and OFF.			
		00	R/W	00	GPIO1			
3:2	curr2_gpio			01	GPIO2			
				10	GPIO3			
				11	NA			
				If bits curr3_ctrl = 1 <i>x</i> , the following pin is assigned for turning the CURR3 pin ON and OFF.				
				00	GPI01			
5:4	curr3_gpio	00	R/W	01	GPIO2			
				10	GPIO3			
				11	NA			
					L_ctrl = 1 <i>x</i> , the following pin is assigned for turning the ON and OFF.			
			R/W	00	GPIO1			
7:6	curr4_gpio	00		01	GPIO2			
				10	GPIO3			
				11	NA			



7.7 Audio Amplifier

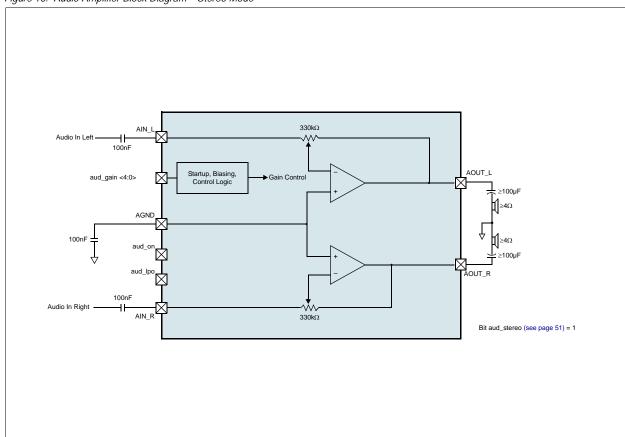
The integrated Audio Amplifier provides real CD-quality audio and can be used as a headphone amplifier for portable devices. It is designed to meet the operational and power requirements of portable devices by delivering:

- 1WRMs continuous power into 8Ω differential at 5V supply
- 2 x 50mWRMs into 32Ω single-ended at 5V supply

The Audio Amplifier provides the following operational features:

- Total harmonic distortion is less than 0.1% at 1kHz and the guiescent current does not exceed 8mA.
- Power supply rejection is always better than 50dB and allows direct connection to noisy batteries, e.g. in TDMA systems.
- The internal programmable gain can be used for volume and balance control.
- Only a few external components are required for AC-coupling and reference bypass.
- An internal smooth-rampup circuit ensures pop- and click-less startup without expensive and bulky external relays.
- Device stability even with high capacitive loads of 1nF and does not require external snubber networks.
- Inputs are high-impedance in power-down.

Figure 16. Audio Amplifier Block Diagram - Stereo Mode



Note: The value of the audio output decoupling capacitors depends on the speaker impedance and the desired minimum output frequency:

$$C = 1/(2xPxfxR) (EQ 2)$$

Where:

f = minimum output cutoff frequency, -3dB point.

R = speaker impedance in Ω .

C = decoupling capacitance in F.



Figure 17. Audio Amplifier Block Diagram – Differential Mode

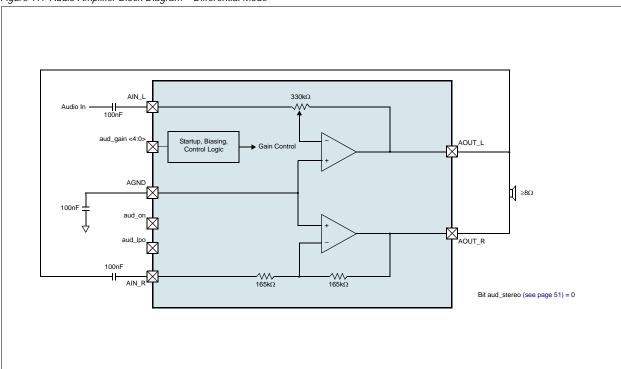


Table 21. Audio Amplifier Characteristics

Symbol	Parameter	Min	Тур	Max	Unit	Notes
VDDH	Supply Voltage Range (VBAT_3)	3		5.5	V	
DCDD	Power Supply Rejection Ratio,		70		40	f = 1kHz
PSRR	Differential		50		dB	f = 20kHz
PSRR	Power Supply Rejection Ratio, Single-		50		dB	f = 1kHz
PSKK	Ended		40		UB	f = 20kHz
loff	Shut Down Current			100	nA	
				9		aud_lpo = 0 and aud_ib_red = 00
IVDDH	Supply Current (Differential Mode)			4	mA	aud_lpo = 1 and aud_ib_red = 00
	,			2.7		aud_lpo = 1 and aud_ib_red = 11
				8		aud_lpo = 0 and aud_ib_red = 00
IVDDH	Supply Current (Stereo Mode)			3	mA	aud_lpo = 1 and aud_ib_red = 00
				1.7		aud_lpo = 1 and aud_ib_red = 11
Rload	Output Load	8			Ω	Differential mode
RLOAD	Output Load	4			1 22	Stereo mode
				0.1	%	Pout = 1W, RLOAD = 8Ω , f = 1kHz, VBAT = 5.5V; Differential
THD+N	Total Harmonia Dictortian			0.5	%	Pout = 1W, RLoad = 8Ω , f = $20kHz$, VBAT = $5.5V$; Differential
I HD+N	Total Harmonic Distortion			0.05	%	Pout = 50mW, RLOAD =32 Ω , f = 1kHz, VBAT = 4V; Single-Ended
				0.2	%	POUT = 50mW, RLOAD = 32Ω , f = 20kHz, VBAT = 4V; Single-Ended



Table 21. Audio Amplifier Characteristics (Continued)

Symbol	Parameter	Min	Тур	Max	Unit	Notes
SNR	Signal to Noise Ratio	84	91		dB	VBAT=3.7V, not tested, guaranteed per design
A0	Gain	-22	0	20	dB	Programmable gain: AOUT/AIN
ΔАх	Programmable Gain Step-Size		3		dB	
IOV_ON	Overcurrent On_limit	591	650	744	mA	Current rising into PMOS driver; when aud_lpo = 0 and aud_ib_red = 00, and aud_overcur = 1.
lov_off	Overcurrent Off_limit	397	550	650	mA	Current decreasing in PMOS driver; when aud_lpo = 0 and aud_ib_red = 00, and aud_overcur is cleared.
lov_hyst	Overcurrent Hysteresis		100		mA	

7.7.1 Audio Amplifier Registers

Bit definition for Audio amplifier registers are given below.

Audio Control Register (Address 2Bh).

Addr: 2Bl	•	Audio Control							
Addr: 2Bi	П	Configures the A	Audio Amplifier.						
Bit	Bit Name	Default	Access	Bit Descr	Bit Description				
				Activates the Audio Amplifier.					
0	0 aud_on 0		R/W	0	Audio amplifier off; inpu impedance.	ts AIN_L ar	nd AIN_R are high-		
				1	Audio amplifier on.				
				Select Lov	v-Power Operation; reduc	ed output p	oower.		
1	1 aud_lpo 0 R/W		0	Use for speakers $< 32\Omega$ mode; $< 64\Omega$ differentia		mpedance) in stereo			
				1	Use for speakers $\geq 32\Omega$ (nominal impedance) in stereo mode; $\geq 64\Omega$ differential.				
		00b	R/W	Reduced bias current into Audio Amplifier circuit.					
	aud_ib_red			00	Use for speakers < 8Ω (nominal impedance) in stereo mode; < 16Ω differential.				
3:2				01	NA				
				10	NA				
				11	Use for speakers $\geq 8\Omega$ (nominal impedance) in stereo mode; $\geq 16\Omega$ differential.				
				Audio Am	plifier gain adjust.				
				0000	Output off	1000	0dB		
				0001	-22dB	1001	+2dB		
				0010	-19dB	1010	+5dB		
7:4	aud_gain	0000b	R/W	0011	-16dB	1011	+8dB		
				0100	-13dB	1100	+11dB		
				0101	-10dB	1101	+14dB		
				0110	-7dB	1110	+17dB		
				0111	-4dB	1111	+20dB		



Audio Control 2 Register (Address 41h).

Addr: 41h	1	Audio Control	2					
Audi. 411	•	Configures the Audio Amplifier.						
Bit	Bit Name	Default	Access	Bit Description				
				Selects aud	lio mode.			
0	aud_stereo	1	R/W	0	Differential mono mode (connect pin AIN_R to pin AOUT_L)			
				1	Stereo mode.			
1	aud_overcur	0	0 R		Normal operation; audio output current below limit of IOV_ON.			
				1	Audio output current exceeds limit (IOV_ON).			
				Audio ampl	ifier output pulldown control; active if aud_on=0.			
				00	30µA			
3:2	aud_pulldwn	00b	R/W	01	0.6mA			
			10	1.2mA				
				11	2.5mA			
7:4	-	NA	Na					



8 System Supervisory Functions

8.1 Reset

XRES is an active low bi-directional pin; an external pullup to LDO VANA_1 has to be added (see Digital Input/Output DC/AC Characteristics on page 61). During each reset cycle the following states are controlled by the AS3605:

- Pin XRES is Forced to GND
- Programmable Power-off Function
- Programmable Power-on Sequence and Regulator Voltages
- Programmable Reset Timer
- All Register bits Set to Default Values after Power-On (except the Audio Control 2 (page 51), the Interrupt Status (page 43).

Note: Programming is controlled by the internal OTP-ROM.

8.1.1 Reset Conditions

Reset can be activated from 7 different sources:

- Power On (Battery or Charger Insertion)
- Low Battery
- Power Off Mode
- Software Forced Reset
- Externally Triggered through the XRES Pin
- Overtemperature
- Watchdog
- Momentary Power Loss Detection

Power On (Battery or Charger Insertion). There are two types of voltage dependent resets:

- VPOR Monitors the voltage on pin V2_5. LDO V2_5 uses the voltage VCHARGER or VBAT as its source.
- VRESET Monitors the voltage on VBAT pins. Pin XRES is only released if V2_5 > VPOR and VBAT > VRESETRISE.

Low Battery. A reset is automatically generated if VBAT drops below VRESETFALLING for a minimum period (VRESETMASk).

Table 22. Reset Levels

Symbol	Symbol Parameter		Тур	Max	Unit	Notes
VPOR Overall power on reset		1.5	2.0	2.3	V	Monitor voltage on pin V2_5; power on reset for all internal functions. Pin RESET stays low until V2_5 > VPOR
VRESETRISE Reset level for VBAT rising			3.1		٧	Monitor voltage on pin VBAT; rising level.
VRESETFALLING Reset level for VBAT falling 1			2.8		٧	Monitor voltage on pin VBAT; falling level.
VRESETMASK	Mask time for VRESETFALLING		40		μs	Duration for VBAT < VRESETFALLING until a reset cycle is started ² .
Tpowerloss	Interval for recovery of power loss on VBAT	100	250	500	ms	If the duration of a power loss on VBAT is below this duration, the system will restart

^{1.} VRESETFALLING is only accepted if the reset condition is longer than VRESETMASK. This guard time is used to avoid a complete reset of the system in case of short drops of VBAT.

^{2.} VRESET signal is debounced with the specified mask time for rising- and falling-slope of VBAT. The default time is 40μ s and it can be programmed from 0μ s to 200μ s with the register reset-mask timer.



Power Off. Setting bit **power_off** = 1 puts the AS3605 into ultra low-power mode. To start a complete reset cycle, the AS3605 waits until the external pin ON is pulled high, the Battery Charger is inserted, or level VPOR is reached. Bit **power_off** is automatically cleared by this reset cycle. During power off state, all circuits are turned off except LDO V2_5, thus the current consumption of the AS3605 is reduced to less than 10μA. The digital part is supplied by LDO V2_5, all other circuits are turned off in this mode, including internal references and oscillator.

Note: All registers except the Reset Control on page 53 are set to their default value after power-on.

Software Forced Reset. Setting bit force_reset = 1 immediately initiates a reset cycle, and is automatically cleared during a reset.

External Triggered Reset. If the pin XRES is pulled from high to low by an external source (microprocessor or button) a reset cycle is initiated.

Overtemperature Reset. The reset cycle can be started by overtemperature conditions (see page 55).

Watchdog Reset. If the Watchdog is armed (bit **wtdg_on** = 1 and bit **wtdg_res_on** = 1) and the timer expires, a reset is initiated. Refer to page 57 for information about the Watchdog block.

8.1.2 Reset Registers

Bit definition for Reset registers are given below.

Reset Control Register (Address 3Ah).

Addr: 3A	h	Reset Contr	ol		
Addi: 3A	M1	Controls rese	et and power of	f.	
Bit	Bit Name	Default	Access	Bit Descri	iption
0	force recet	0	DM	0	Normal operation.
0	force_reset	0	R/W	1	Initiates a complete reset cycle.
			0		Normal operation.
1	power_off	0	R/W	1	Initiates power-off mode where all LDOs are turned off except LDO V2_5. The AS3605 waits for a rising edge on pin ON or until the battery charger is detected.
				Static indic	cation of ON input pin.
2	on_input	0	R	0	ON input pin is low.
					ON input pin is high (external ON key depressed).
				Indicates t	o the software the reason for the most recent reset.
				000	VPOR was reached (initial battery or charger insertion)
				001	VRESETFALLING was reached (VBAT < 2.75V)
				010	Software forced by bit force_reset
5:3	reset_reason	0h	R	011	Software forced by bit power_off and a Battery Charger detected
				100	Software forced by bit power_off and ON was pulled high
				101	Externally triggered through pin XRES
				110	Reset caused by overtemperature T140
				111	Reset caused by Watchdog
6	tmp pwr lose	0	0 0		Normal startup.
U	tmp_ pwr_loss	U	R	1	A momentary power loss condition was detected.
7	-	NA	NA		



Reset Timer Register (Address 13h).

Addr: 13	h	Reset Timer					
Auui. 13	(1)	Sets the RESE	T timer value.				
Bit	Bit Name	Default	Access	Bit Descript	Bit Description		
				Set RESTIME			
				000	RESTIME = 0ms		
				001	RESTIME = 10ms		
				010	RESTIME = 20ms		
2:0	res_timer	OTP	R/W	011	RESTIME = 30ms		
				100	RESTIME = 40ms		
			101	RESTIME = 50ms			
			110	RESTIME = 60ms			
				111	RESTIME = 70ms		
				Set MASKTIME			
				000	MASKTIME = 0µs		
				001	MASKTIME = 5µs		
				010	MASKTIME = 10µs		
5:3	reset_mask_timer	OTP	R/W	011	MASKTIME = 40µs		
				100	MASKTIME = 80µs		
				101	MASKTIME = 120µs		
			110	MASKTIME = 160µs			
				111	MASKTIME = 200µs		
7:6	-	NA	NA				

8.1.3 Reset Cycle

During a reset cycle, pin XRES is forced low for at least the time specified by bits **res_timer** and then all register bits are set to their default values except bit **ov_temp_140**.

During the reset time, a normal startup is initiated (refer to Startup on page 55) and the reset is active until the reset timer (set by bits **res_timer**) expires. The voltage on pin XRES is then pulled high by the external resistor and the whole system is leaving the reset state.

8.1.4 res_con: Reset Control

Reset is internally generated from a power on detection circuit (see page 52) and provided to the internal logic as well as externally through the open-drain pin XRES. This pin can also be forced externally by pulling it low. Additionally Reset can be forced by software by setting bit **force_reset** = 1.



8.2 Startup

8.2.1 Normal Startup

During a normal reset cycle (see page 52), after V2_5 is above VPOR and VBAT is above VRESETRISE, a normal startup is initiated as follows:

- 1. The external capacitor on pin CREF is charged to 1.8V.
- 2. The DC/DC converters and LDOs are sequentially powered up according to the Boot OTP configuration.
- 3. Depending on the Boot OTP setting (Auto-Shutdown):
 - a) The AS3605 enters shutdown mode if no momentary power loss is detected (only valid through initial start-up, not during a reset cycle).

-or-

b) The Reset-Timer is set by the Boot OTP and the reset is released when the Reset-Timer expires (pin XRES is pulled high).

8.2.2 Programmable Startup Sequences

The start-up segunece is factory programmed. For more details please contact austriamicrosystems AG.

8.2.3 Startup from Battery Charger

If the voltage on pin VCHARGER is within VSTARTCHARGER, the Battery Charger is started in all cases, even with VBAT = 0V. This allows the battery to be charged (even from deep discharge) and a normal startup to proceed.

Table 23. Battery Charger Startup Conditions

Symbol	Parameter	Min	Тур	Max	Unit	Notes
VSTARTCHARGER	Voltage on pin VCHARGER for the AS3605 to start	4.35	5.0	15	V	On pin VCHARGER.

8.3 Protection Functions

The Step Down DC/DC Converter, and all LDOs have integrated overcurrent protection. Overtemperature protection of the AS3605 is also built-in and can be activated with the serial interface bit **temp_pmc_on**.

The AS3605 has two temperature indicators:

- ov_temp_110 Automatically reset if the overtemperature condition is removed.
- ov_temp_140 Must be reset via the serial interface with bit rst_ov_temp_140. If ov_temp_140 is set, an automatic reset of the complete AS3605 is initiated. Bit ov_temp_140 is not cleared by this reset cycle to indicate the reason for this (unexpected) shutdown. It must be cleared intentionally by bit rst_ov_temp_140. The cause of this reset is stored in the Reset Control (page 53). This allows a detection of the reset cause, after the device has restarted.

8.3.1 TMP_SV: Temperature Supervision

The AS3605 includes an integrated temperature sensor, implemented to provide overtemperature protection of the device. It generates flags linked to the two temperature thresholds:

- T110 110° threshold. Sets ov_temp_110, signalling the 110° overtemperature condition. Thus software can react and shut down power-consuming functions in order to decrease the device's temperature.
- T140 140° threshold. Reaching this temperature level generates a Reset, when temp_pmc_on is enabled. This sets all regulators into power-down mode and stops battery charging.



8.3.2 Overtemperature Detection

Table 24. Overtemperature Detection Parameters

Symbol	Parameter	Min	Тур	Max	Unit
T110	ov_temp_110 Rising Threshold	95	110	125	°C
	ov_temp_110 Kising Threshold	203	230	257	٥F
T140	August 440 Dieing Throchold	125	140	155	°C
	ov_temp_140 Rising Threshold	257	284	311	°F
Thyst	ov_temp_110 and ov_temp_140 Hysteresis		5		°C

8.3.3 Overtemperature Detection Register

Overtemperature Control Register (Address 3Bh).

Addr: 3Bl	.	Overtemperatu	ire Control					
Addi: 3bi	n	Device temperature supervision.						
Bit	Bit Name	Default	Access	Bit Description				
			0 R/W	Activates/deactivates temperature supervision. Default: Off - all other bits are only valid if set to 1.				
0	temp_pmc_on	0		0	Temperature supervision is disabled. No reset will be generated when the device temperature exceeds 140°C.			
				1	Temperature supervision is enabled.			
1	ov_temp_110	0	R	1	Warning flag indicating that the device temperature has exceeded 110°C.			
2	ov_temp_140	0	R	1	Indicates that the device overtemperature has exceeded 140°C. This bit is not cleared by the automatic reset caused by this flag. It must be cleared using bit rst_ov_temp_140.			
3	rst_ov_temp_140	0	R/W	Used to cl	ear bit ov_temp_140 ; first set this bit = 1 and then set it =0.			
4	temp_test0	0	R/W	Only used	for production; must always be set to 00.			
5	temp_test1	0	R/W					
6	tco_110_a	0	R	Only used	Only used for production – direct output of T110 comparator.			
7	tco_140_a	0	R	Only used for production – direct output of T140 comparator.				



8.4 Watchdog Block

The AS3605 includes a Watchdog block to detect a deadlock of the connected controller.

If the Watchdog block is active (**wtdg_on** = 1), it must get a continuous trigger signal within a programmable timer window. If there is no signal for a certain time period from a defined GPIO pin or bit **wtdg_sw_sig**, the Watchdog block starts either a complete reset – bit **wtdg_res_on** must be set to 1 – or sets interrupt flag **wdog_i**.

The Watchdog timer window is defined by bits:

- wtdg_min_timer
- wtdg_max_timer

The trigger signal can be configured using bits:

- wtdg_trigger
- wtdg_sw_sig Watchdog is reset by software
- wtdg_gpio_input Watchdog is reset by hardware (GPIO)

Any of the general purpose input/outputs can be configured as inputs using bit **wtdg_gpio_input**, and outputs using bits **gpio1_out_src**, **gpio2_out_src**, or **gpio3_out_src** = 11, for the Watchdog. While the GPIO input must be continuously re-triggered in order to avoid a Watchdog interrupt, the GPIO output will generate in interrupt when the Watchdog runs over – **wdog_int_en**.

8.4.1 Watchdog Registers

The Watchdog is controlled by the registers listed in Table 25.

Table 25. Low Dropout Regulators Register Summary

Name	Addr	b7	b6	b 5	b4	b3	b2	b1	b0	Page
Watchdog Control	2Eh		-		wtdg_ trigger	wtdg_gp	oio_input	wtdg_ res_on	wtdg_on	57
Watchdog_min Timer	2Fh	wtdg_min_timer				58				
Watchdog_max Timer	30h		wtdg_max_timer					58		
Watchdog Software Signal	31h	- wtdg_ sw_sig				58				

Watchdog Control Register (Address 2Eh).

Addr. 2Ek	Addr: 2Eh		Watchdog Control					
Audi. ZEII		Controls the Watchdog block.						
Bit Bit Name		Default	Access	Bit Description				
0	utda on	0	0 P/M	0	Disables the Watchdog block.			
0	0 wtdg_on 0 R/W		K/VV	1	Enables the Watchdog block.			
					log expires and this bit = 1, a reset cycle will be started. Refer or information about reset cycles.			
1	1 wtdg_res_on 1 R/W	R/W	0	A watchdog overflow does not generate a reset.				
				1	A watchdog overflow generates a reset.			



Addr: 2Eh		Watchdog Con	trol				
Auui. ZEi	1	Controls the Watchdog block.					
Bit	Bit Name	Default	Access	Bit Description			
				Specifies th	ne input pin of the Watchdog if bit wtdg_trigger = 1.		
	3:2 wtdg_gpio_input 00		00	GPIO1			
3:2		R/W	01	GPIO2			
			10	GPIO3			
				11	Do not use this setting.		
				Select type	of trigger (software or hardware).		
4	wtdg_trigger	0	R/W	0	Use bit wtdg_sw_sig as trigger signal for the Watchdog.		
	, mag_uiggor	1	Use the pin defined by bit wtdg_gpio_input as trigger signal for the Watchdog.				
7:5	-	NA	NA				

Watchdog_min Timer Register (Address 2Fh).

Addr: 2Fh		Watchdog_min Timer					
		Sets the minimum Watchdog trigger time.					
Bit Bit Name		Default	Access	Bit Descript	ion		
		00 _h	R/W	00 _h	0s		
7:0	wtdg_min_timer			01 _h	16ms		
7.0	7.0 wtug_mm_timer						
				FFh	4.08s		

Watchdog_max Timer Register (Address 30h).

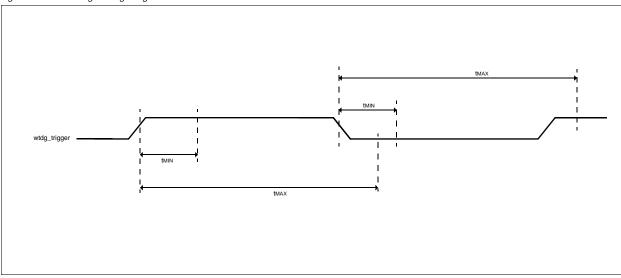
Addr: 30h		Watchdog_max Timer					
Addi. 3011		Sets the maxim					
Bit Bit Name		Default	Access	Bit Descript	ion		
	7:0 wtdg_max_timer F		R/W	01 _h	16ms		
7:0		FF _h					
7.0		ı ı n		FF _h	4.08s		
				Caution:	Do not set these bits = 00_h		

Watchdog Software Signal Register (Address 31h).

Addr: 21h	Addr: 31h		Watchdog Software Signal						
Addi. 3111		Resets the Water	Resets the Watchdog block by software.						
Bit	Bit Name	Default	Access	Bit Description					
				Trigger input by the serial interface if wtdg_trigger = 0					
0	wtdg_sw_sig	0	R/W	0	Force watchdog trigger = low (see Figure 18)				
				1	Force watchdog trigger = high (see Figure 18)				
7:1	-	NA	NA						



Figure 18. Watchdog Timing Diagram



8.5 Internal Reference Circuits

The internal reference circuits (V, I, fclk) require the external components listed in Table 26.

Table 26. Reference External Components

Symbol	Parameter	Min	Тур	Max	Unit	Notes
Сехт	External filter capacitor	-20%	100	+20%	nF	Ceramic low-ESR capacitor between pins CREF and VSS

Table 27. References Characteristics

Symbol	Parameter	Min	Тур	Max	Unit	Notes
VCEXT	Reference voltage	-1%	1.8	+1%	V	Low noise trimmed voltage reference - connected to pin CREF; do not load.
fCLK	Internal reference clock	1.0	1.1	1.2	MHz	Trimmed clock reference

To reduce the current consumption of the AS3605, internal references circuits can be set into a special low-power mode with bit **low_power_on**.



8.5.1 Internal Reference Registers

References Control Register (Address 2Dh).

Addr: 2DI	h	References Co	ntrol			
Addi: 2Di	П	Configures low-	power mode.			
Bit	Bit Name	Default	Access	Bit Descrip	otion	
0	low_power_on	0	R/W	0	Standard mode or controlled by GPIO, if low_power_gpio_on = 1.	
U	low_power_orr	0		1	Low-power mode; all parameters except noise (see LDO parameters, section 7.3) are still valid.	
				If set and Ico	pw_power_on = 0 then the low-power mode is controlled pin.	
1	low_power_gpio_on	0	R/W	0	Low-power mode disabled for GPIO control.	
'	юп_ропог_дрю_оп			1	Low-power mode is activated by GPIO pin (low_power_gpio). low_power_on must be enabled.	
			R/W	Specifies the pin to be used as GPIO control.		
				00	GPI01	
3:2	low_power_gpio	00		01	GPIO2	
				10	GPIO3	
				11	GPIO3	
4	low power anic nel	0	D/W	0	Low-power mode is activated. If the selected GPIO input, bit low_power_gpio = 1.	
4	4 low_power_gpio_pol 0		R/W	1	Low-power mode is activated. If the selected GPIO input, bit low_power_gpio = 0.	
7:5	-	NA	NA			

8.6 Low Power Mode

Bit **low_power_on** controls low-power mode. In low-power mode the integrated voltage reference and the temperature supervision comparators operate in pulsed mode. This reduces the quiescent current of the AS3605 by 45µA (typical). Because of the pulsed function, the LDO output noise parameters do not meet the specification in low-power mode but the full functionality is still available.

Note: Low-power mode can be activated by hardware using one of the GPIO pins, or by software by setting bit **low_power_on** = 1.



8.7 Serial Interface

8.7.1 Digital Input/Output DC/AC Characteristics

VBAT_1 is used as supply voltage of the pins.

Table 28. DC Characteristics Input Pin SCK

Symbol	Parameter	Min	Max	Unit	Notes
VIH	High-Level Input Voltage	1.5	VBAT	V	
VIL	Low-Level Input Voltage		0.4	V	
ILEAK	Input Leakage Current	-5	5	μA	to VBAT_1 and GND_PAD

Table 29. DC Characteristics Open Drain Pin SDA

Symbol	Parameter	Min	Max	Unit	Notes
Vih	High-Level Input Voltage	1.5		V	
VIL	Low-Level Input Voltage		0.4	V	
ILEAK	Input Leakage Current	-5	5	μΑ	to VBAT_1 and GND_PAD
Vol	Low-Level Output Voltage		0.2	V	at 4.0mA
CLOAD	Capacitive Load		50	pF	

Table 30. DC Characteristics Input/Output Open Drain Pin XRES

Symbol	Parameter	Min	Max	Unit	Notes
VIH	High-Level Input Voltage	1.5		V	
VIL	Low-Level Input Voltage		0.4	V	
ILEAK	Input Leakage Current	-5	5	μA	to VANA_1 and GND_PAD
Vol	Low-Level Output Voltage		0.2	V	at 4mA
CLOAD	Capacitive Load		50	pF	
RPULLUP	External Pullup Resistor		100k	Ω	Connect to <=VBAT_1



8.7.2 I²C Compatible Serial Interface

The following pins are used for the I²C interface:

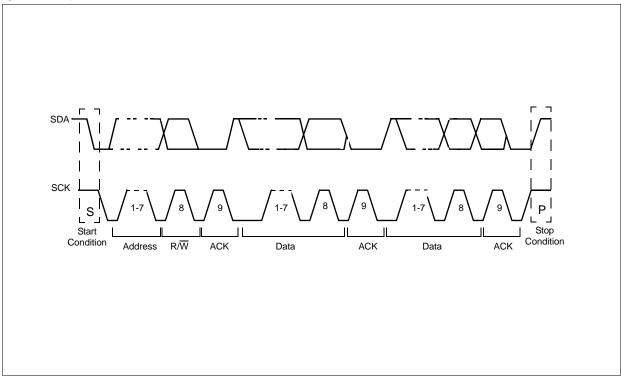
- SDA = I/O Pin
- SCK = Input Pin

FC Features. Listed below are I²C features:

- Fast-mode capability (max. SCL-frequency is 400 kHz @ 100pF capacitive load)
- 7-bit addressing mode
- Write formats:Single-Byte-Write, Page-Write
- Read formats:Current-Address-Read, Random-Read, Sequential-Read
- SDA input delay and SCL spike filtering by integrated RC-components

FC Slave Addresses. The AS3605 device address is fixed at 82_h for write commands and 83_h for read commands.

Figure 19. Complete Data Transfer





FC Data Transfer Formats. Definitions used in the serial data transfer format diagrams (Figures 20 - 24) are listed in Table 31.

Table 31. ²C Data Transfer Byte Definitions

Symbol	Definition	R/W (AS3605 Slave)	Notes
S	Start condition after stop	R	1 bit
Sr	Repeated start	R	1 bit
DW	Device address for write	R	1000 0010 (82 _h)
DR	Device address for read	R	1000 0011 (83 _h)
WA	Word address	R	8 bit
А	Acknowledge	W	1 bit
N	No acknowledge	R	1 bit
reg_data	Register data/write	R	8 bit
data (n)	Register data/read	R	1 bit
Р	Stop condition	R	8 bit
WA++	Increment word address internally	R	During acknowledge

Figure 20. ²C Byte Write

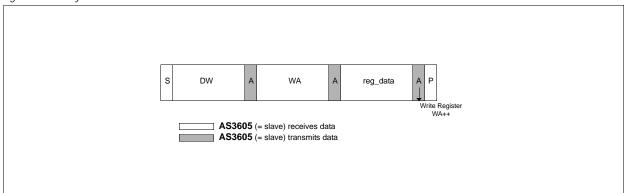
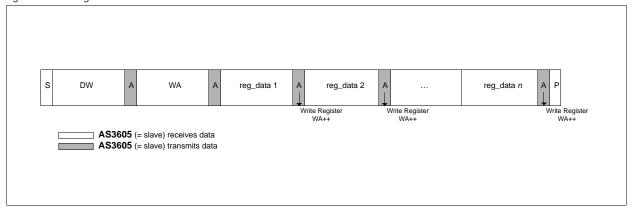


Figure 21. PC Page Write



Byte Write and Page Write formats are used to write data to the slave.

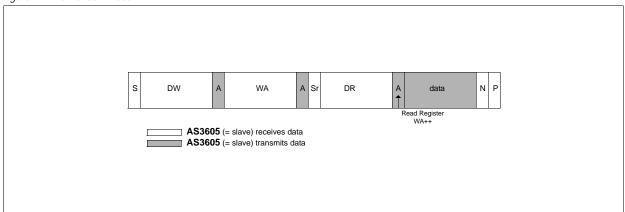
The transmission begins with the START condition, which is generated by the master when the bus is in IDLE state (the bus is free). The device-write address is followed by the word address. After the word address any number of data bytes can be sent to the slave. The word address is incremented internally, in order to write subsequent data bytes on subsequent address locations.



For reading data from the slave device, the master has to change the transfer direction. This can be done either with a repeated START condition followed by the device-read address, or simply with a new transmission START followed by the device-read address, when the bus is in IDLE state. The device-read address is always followed by the 1st register byte transmitted from the slave. In Read Mode any number of subsequent register bytes can be read from the slave. The word address is incremented internally.

The following diagrams show some of the serial read formats supported by the AS3605.

Figure 22. PC Random Read

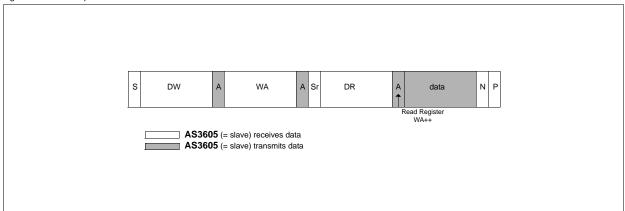


Random Read and Sequential Read are combined formats. The repeated START condition is used to change the direction after the data transfer from the master.

The word address transfer is initiated with a START condition issued by the master while the bus is idle. The START condition is followed by the device-write address and the word address.

In order to change the data direction a repeated START condition is issued on the 1st SCL pulse after the acknowledge bit of the word address transfer. After the reception of the device-read address, the slave becomes the transmitter. In this state the slave transmits register data located by the previous received word address vector. The master responds to the data byte with a not-acknowledge, and issues a STOP condition on the bus.

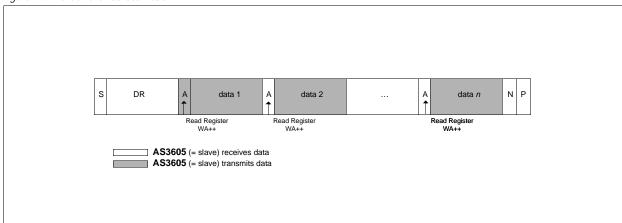
Figure 23. PC Sequential Read



Sequential Read is the extended form of Random Read, as more than one register-data bytes are transferred subsequently. In difference to the Random Read, for a sequential read the transferred register-data bytes are responded by an acknowledge from the master. The number of data bytes transferred in one sequence is unlimited (consider the behavior of the word-address counter). To terminate the transmission the master has to send a not-acknowledge following the last data byte and generate the STOP condition subsequently.



Figure 24. ²C Current Address Read



To keep the access time as small as possible, this format allows a read access without the word address transfer in advance to the data transfer. The bus is idle and the master issues a START condition followed by the Device-Read address. Analogous to Random Read, a single byte transfer is terminated with a not-acknowledge after the 1st register byte. Analogous to Sequential Read an unlimited number of data bytes can be transferred, where the data bytes has to be responded with an acknowledge from the master. For termination of the transmission the master sends a not-acknowledge following the last data byte and a subsequent STOP condition.



9 Register Map

The AS3605 registers along with their addresses and default values are listed in Table 32. Fields marked NA are not used; reading these bits may result in 0s or 1s. Always use 0s, when writing to these bits.

Caution: Do not write to addresses not listed in Table 32.

Table 32. Register Summary

Register	Addr	Default	b7	b6	b5	b4	b3	b2	b1	b0	
Step Down Voltage/ Test Modes	01h	00 _h	-			buck_v					
LDO_RF1 Voltage	02h	00 _h		-		ldo_rf1_v					
LDO_RF2 Voltage	03h	00 _h		-				ldo_rf2_v			
LDO_RF3 Voltage	04h	00 _h		-				ldo_rf3_v			
LDO_RF4 Voltage	05h	00 _h		-				ldo_rf4_v			
LDO_ANA2_Voltag e	06h	00 _h		-				ldo_ana2_v			
LDO_ANA1_Voltag e	07h	00 _h		-				ldo_ana1_v			
LDO_SIM_Voltage	08h	00 _h	NA	ldo_sim_v			-				
Reg Power	09h	00 _h		-	buck_on	ldo_sim_on	-	-	ldo_ana2_ on	ldo_ana1 _on	
LDO_GPIO Active	0Fh	00 _h	-	-	ldo_rf4_gpi o	ldo_rf3_gpi o	Ldo_rf2_gp io	ldo_rf1_gpi 0	ldo_ana2_ gpio	buck_gpio	
LDO_RF Switch	10h	00 _h	ldo_rf4_on ldo_rf3_on ldo_rf2_on ldo_rf1_on EOCCu			EOCCui	rent[1:0]	ana2_sw	ana1_sw		
LDO_AD GPIOx	11h	00 _h	- Ido_ana:			ldo_ana2	_gpio_sel	buck_g	pio_sel		
LDO_RF GPIOx	12h	00 _h	ldo_rf4_gpio_sel ldo_rf3_			gpio_sel	ldo_rf2_	gpio_sel	ldo_rf1_	gpio_sel	
Reset Timer	13h	00 _h		-	res	set_mask_tim	er		res_timer		
ChargerControl1	14h	EDh	ChOvEn	TrickleCu	urrent[1:0]		ConstantCurrent[3:0] ChEn				
ChargerControl2	16h	58h	ChOv	ChOvH	-	Li4v2	resume_dis able				
Step Down Config	17h	00 _h	buck_dis_c urmin	buck_dis_p on	buck_lpo	-	-	buck_dis_n	buck_nsw _on	buck_psw _on	
Charge Pump Control Onkey Pulldown	18h	00 _h	cp_auto_on	cp_start_de bounce	onkey_pulld _off	cp_freq	cp_mode_s witching	cp_mo	de[1:0]	cp_on	
CURR5 Control GPIO Map	19h	00 _h			-		curr5	_gpio	currs	5_ctrl	
GPIO1 Control	1Ah	00 _h	gpio1_	gpio1_out_src gpio1_invert			_pulls	gpio1_low_ curr	gpio1_	_mode	
GPIO2 Control	1Bh	00 _h	gpio2_out_src gpio2_invert			gpio2	_pulls	gpio2_low_ curr	gpio2_	_mode	
GPIO3 Control	1Ch	00 _h	gpio3_out_src gpio3_invert			gpio3_pulls gpio3_low_ curr			gpio3_mode		
Interrupt Enable	1Fh	FEh	chgov_int_ en	chgrmv_int _en	resume_int chdet_int_e onkey_int_ _en n en		ovtmp_int_ en	eoc_int_e n	wdog_int_ en		
Interrupt Status	20h	NA	chgov _i	chgrmv_i	resume_i	chdet_i	onkey_i	ovtmp_i	eoc_i	wdog_i	
GPIO Signal	21h	NA			-			gpio3	gpio2	gpio1	



Table 32. Register Summary

Register	Addr	Default	b7	b6	b5	b4	b3	b2	b1	b0
GPIO Frequency Control High Time	22h	00 _h				gpio_h	_time			
GPIO Frequency Control Low Time	23h	00 _h				gpio_l_	time			
CURR1 value	24h	00 _h				curr1_c	urrent			
CURR2 value	25h	00 _h				curr2_c	urrent			
CURR3 value	26h	00 _h				curr3_c	urrent			
CURR4 value	27h	00 _h				curr4_c	urrent			
CURR control	28h	00 _h	curr	1_ctrl	curr3	3_ctrl	curr2	2_ctrl	curr1	_ctrl
CURR5 value	29h	00 _h				curr5_c	urrent			
CURR GPIO map	2Ah	00 _h	curr4	_gpio	curr3	_gpio	curr2	_gpio	curr1	_gpio
Audio Control	2Bh	00 _h		aud	_gain		aud_i	ib_red	aud_lpo	aud_on
References Control	2Dh	00 _h		NA		low_power _gpio_pol	low_power_gpio		low_power _gpio_on	low_powe r_on
Watchdog Control	2Eh	02h		NA wtdg_trigge				wtdg_gpio_input		wtdg_on
Watchdog_min Timer	2Fh	00 _h				wtdg_mir	_timer			
Watchdog_max Timer	30h	FFh			W	tdg_max_time	er			
Watchdog Software Signal	31h	00 _h				NA				wtdg_sw_ sig
ChargerStatus	35h	NA	-	NoBat	EOC	CVM	Trickle	-	ChAct	ChDet
CP Mode Switch	36h	NA		-		curr5_on_c p	curr4_on_c p	curr3_on_c p	curr2_on_ cp	curr1_on_ cp
Curr Low Voltage Status	37h	NA		-		curr5_low_ volt	curr4_low_ volt	curr3_low_ volt	curr2_low _volt	curr1_low _volt
Reset Control	3Ah	0h	NA	NA tmp_ pwr_loss reset_rease				on_input	power_off	force_res et
Overtemperature Control	3Bh	00 _h	tco_140_a tco_110_a temp_test1 temp_test0			rst_ov_tem p_140	ov_temp_1 40	ov_temp_ 110	temp_pm c_on	
ASIC ID 1	3Dh	33h	0 0 1 1 0 0 1						1	
ASIC ID 2	3Eh	53h		Rev						
Audio Control 2	41h	0h			-		aud_p	oulldwn	aud_overc urr	aud_stere 0

Read Only



68 - 73

10 External Parts List

The recommended specifications for external components (refer to Figure 1 and Figure 2) are listed below.

Table 33. External Parts Specification

Part	Min	Тур	Max	Tol. Min	Rating Min	Remarks	Package Min
C2		470nF		±20%	6.3V	Ceramic, X5R (Charge Pump)	0603
C3	1µF		4.7µF	±20%	6.3V	Ceramic, X5R (V5_6)	0603
C4	1µF		4.7µF	±20%	6.3V	Ceramic, X5R (VANA_1)	0603
C5		1µF		±20%	6.3V	Ceramic, X5R (VBAT_1)	0603
C6	1µF		4.7µF	±20%	6.3V	Ceramic, X5R (VANA_2)	0603
C7	1µF		2.2µF	±20%	6.3V	Ceramic, X5R (V2_5)	1206
C8	1µF		4.7µF	±20%	6.3V	Ceramic, X5R (VRF_1)	0603
С9		1µF		±20%	6.3V	Ceramic, X5R (VBAT_4)	0603
C10	1µF		4.7µF	±20%	6.3V	Ceramic, X5R (VRF_2)	0603
C11	1µF		4.7µF	±20%	6.3V	Ceramic, X5R (VRF_3)	0603
C13	1µF		4.7µF	±20%	6.3V	Ceramic, X5R (VRF_4)	0603
C16		1µF		±20%	6.3V	Ceramic, X5R (VBAT_2)	0603
C18		10µF		±20%	6.3V	Ceramic, X5R (VBUCK)	
C19		100nF		±20%	6.3V	Ceramic, X5R (VSIM)	0402
C20		100µF		±20%	6.3V	Tantalum; L Stereo Decoupling Cap.	
C21		100µF		±20%	6.3V	Tantalum; R Stereo Decoupling Cap.	
C22		1µF		±20%	6.3V	Ceramic, X5R (VBAT_3)	0603
C23		100nF		±20%	6.3V	Ceramic, X5R (Decoupling, AIN_L)	0402
C24		100nF		±20%	6.3V	Ceramic, X5R (Decoupling, AIN_R)	0402
C25		100nF		±20%	6.3V	Ceramic, X5R (AGND)	0402
C26	1µF		4.7µF	±20%	6.3V	Ceramic, X5R (VCHARGER)	0603
C27	10µF			±20%	6.3V	X5R; all VBAT Caps. Combined	0603
C29		100nF		±20%	6.3V	Ceramic, X5R (CREF)	0402
R4	$50 \text{m}\Omega$	100mΩ	150m Ω	±1%		Shunt resistor	0603
R5		100k		±10%		Reset Pullup Resistor	0201
L2		2.2µH		±20%		Recommended type: Coiltronics SD-12-2R2	
Q1	PBSS	301PD or	similar			Charger Transistor	



11 Package Drawings and Markings

Figure 25. QFN40 (5x5mm) Drawings and Dimensions

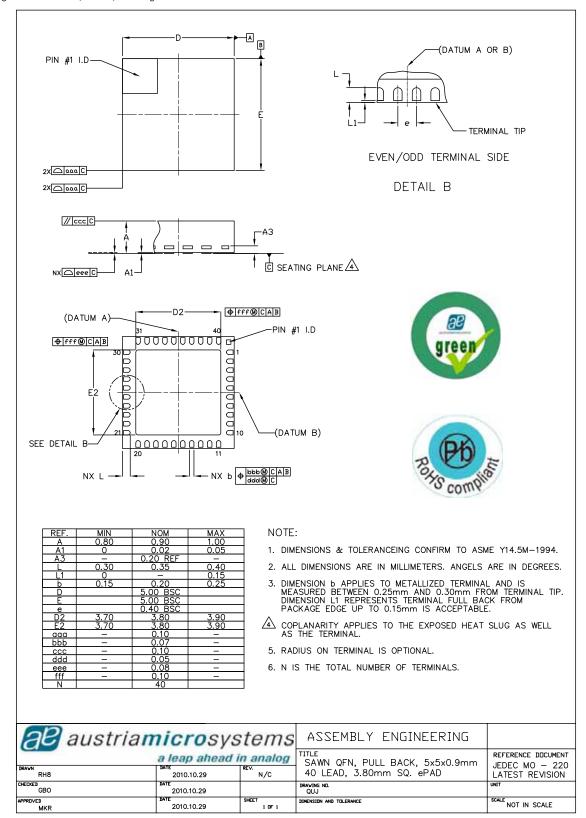




Figure 26. QFN Marking

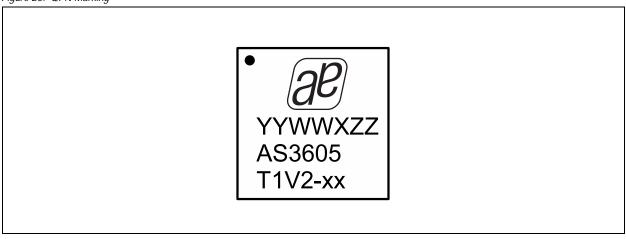


Table 34. Package Code YWWZZZ

YY	WW	Х	ZZ
year	working week assembly / packaging	plant identifier	free choice

Table 35. Start-up Revision Code

XX	Sequence		
FF	engineering samples, no sequence programmed or sequence programmed on request		
XX	customer specified sequence programmed during production test		



71 - 73

Revision History

Revision	Date	Owner	Description	
1.0	March, 2011	pkm	first official release	

Note: Typos may not be explicitly mentioned under revision history.



12 Ordering Information

The devices are available as the standard products shown in Table 36.

Table 36. Ordering Information

Ordering Code	Marking	Description	Delivery Form	Package
AS3605-BQFR-FF	T1V2-FF	Multi Standard PMU - Engineering Samples	Tray	QFN40 5x5mm
AS3605-BQFP-xx	T1V2-xx	Multi Standard PMU - Production Parts Programmed	Tape and Reel (in dry pack)	QFN40 5x5mm

Note: All products are RoHS compliant and austriamicrosystems green.

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Contact Information

Headquarters

austriamicrosystems AG Tobelbaderstrasse 30 A-8141 Unterpremstaetten, Austria

Tel: +43 (0) 3136 500 0 Fax: +43 (0) 3136 525 01

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